



June 2020

Quarterly Reliability Report

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pSemi Reliability System

The Quarterly Reliability Report is a compilation of reliability stress test results that crosses the entire product & technology family of pSemi products. Data is collected on a regular basis through the efforts of product and process qualifications, standard product monitoring and lot acceptance testing. To date, a total of **103,628 devices** have been tested in HTOL with a total of **7.59 billion equivalent device hours**. The overall failure rate for the pSemi family of products is **0.12 FIT**. (Using $E_{a} = 0.7\text{eV}$, $T_j = 55^\circ\text{C}$ at 60% UCL)

pSemi reliability testing standards conform to industry standard qualification procedures as detailed in the JEDEC guidelines. In addition, where clear guidelines have not been established yet, pSemi has developed stringent reliability requirements to ensure consistent high reliability performance.

pSemi makes use of accelerated life testing results, along with thermal acceleration factors in the prediction of failure rates. High Temperature Operating Life (HTOL) stress testing is performed at accelerated voltage and temperature conditions which are based on JEDEC-JESD22-A108 standards. Resulting data collected from HTOL tests is de-rated to a typical use operating junction temperature (T_j) of 55°C . Early Life Failure Rate (ELFR) is derived after 48-hr performance.

pSemi conducts an ongoing product reliability monitoring program to evaluate sample products from high volume, major product families on a quarterly basis. The reliability monitoring process is a continuously improving system within pSemi as we strive for superior product knowledge and performance.

pSemi performs the majority of Reliability testing using an ISO17025 certified test laboratories located in San Jose, CA. Regular auditing of the laboratory is performed to ensure compliance to ISO standards.

Failure Rate Calculation

Acceleration Factor (AF)

For a given failure mechanism, acceleration factor (AF), is the ratio of the time it takes for a certain fraction of the population to fail, following application of one stress or use condition, to the corresponding time at a more severe stress or use condition.

The industry uses the thermal acceleration model formula based on Arrhenius equation noted below:

$$AF(T_{use}, T_{stress}) := e^{\frac{E_{aa}}{k_B} \cdot \left(\frac{1}{T_{use}} - \frac{1}{T_{stress}} \right)}$$

where:

$E_{aa} := 0.7 \text{ eV}$, is the Apparent Activation Energy

$e = 2.718$, is the base of natural logarithm

$k_B := 8.62 \cdot 10^{-5} \frac{\text{eV}}{\text{K}}$, is the Boltzmann constant

T_{use} & T_{stress} , are the use and stress test temperatures, respectively, in Kelvin

Sample Calculation

Find the Acceleration Factor (AF) with the following conditions.

(a) $T_{use} := 55 \text{ }^\circ\text{C}$ and $T_{stress} := 125 \text{ }^\circ\text{C}$

$$AF(T_{use}, T_{stress}) = 77.5$$

(b) $T_{use} := 55 \text{ }^\circ\text{C}$ and $T_{stress} := 150 \text{ }^\circ\text{C}$

$$AF(T_{use}, T_{stress}) = 258.7$$

Failure Rate Calculation (continued)

Failure in Time Calculation

Mean time to failure (M.T.T.F.) is defined as the average time it takes for a failure to occur. Failure in Time (F.I.T.) is the number of units predicted to fail in a billion ($1e^9$) device hours at a specified temperature. After the life test is completed and accelerated device hour data is calculated, the failure rate is estimated using the Chi-Square approximation (χ^2) as follows:

$$FIT = \left(\frac{\chi^{2(2r+2)}}{2 * EDH} \right) * 1e^9$$

where:

χ^2 = chi square function

r = number of failures

EDH = equivalent device hours (units tested x test hours x AF)

Sample Calculation

Given: Units Tested (Sample Size) = 231 devices
 Test temperature = 150°C
 Test duration = 500 hours
 Failures = 0

$EDH = (231 \times 500 \times 259.2) = 2.99E+7$ equivalent device hours

χ^2 @ 60% confidence level and 0 failures = 1.83

FIT (60% confidence level) = $[1.83 / (2 \times 2.99E+7)] \times 1.0E+9 = \underline{30.6 FIT}$

The slide features a white background with a diagonal split. The top-left and bottom-right corners are filled with black, while the top-right and bottom-left corners are white. A thin, light gray diagonal line separates the black and white areas. The title "Technology Classification" is centered in a large, black, sans-serif font.

Technology Classification

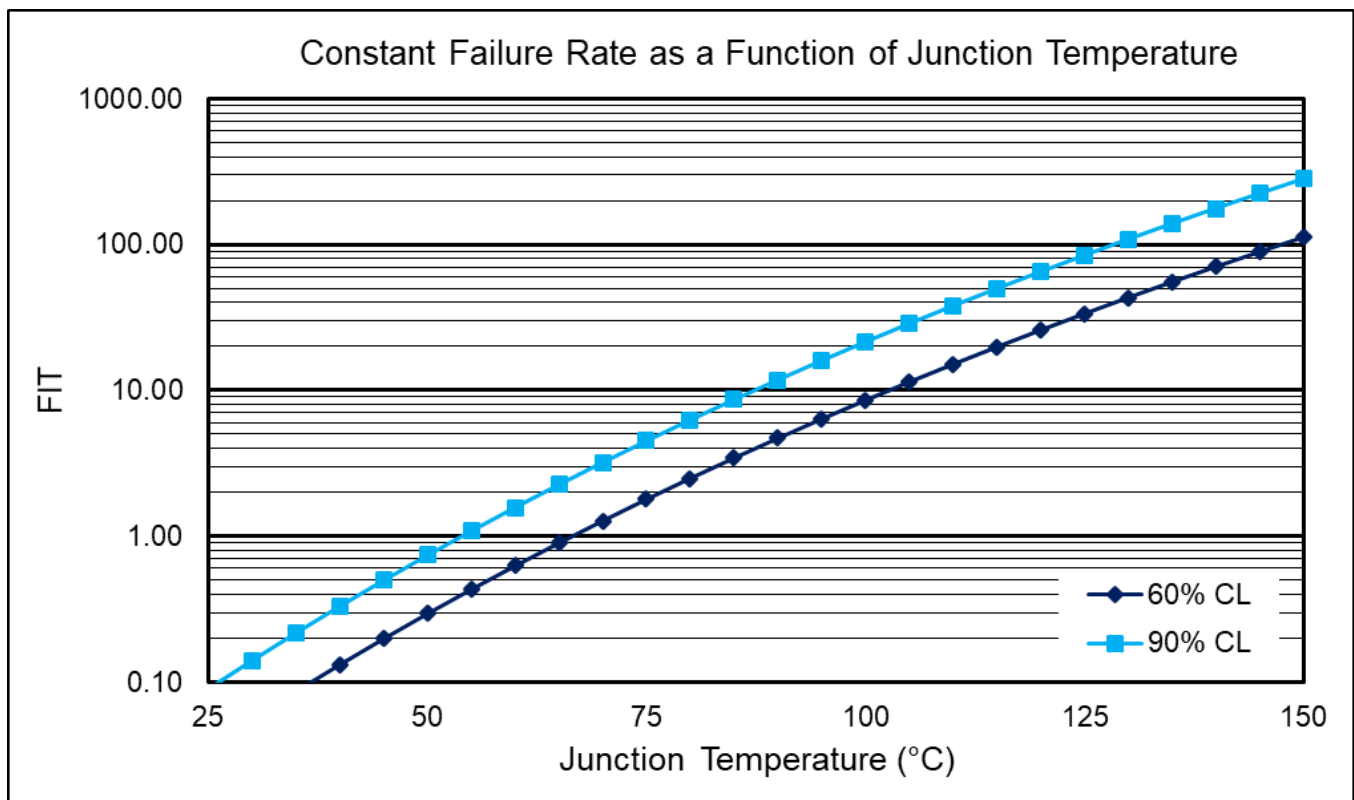
UltraCMOS[®] 2 Process Technology

Generation : 500 nm CMOS Silicon Epi Process (U500E)

Units Tested : 28,340

Product Family : DC-DC, DSA, MXR, PLL, PSR, Switch

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	2.50E+08	3.7	2.73E+08
Constant (Random)	2.12E+09	0.4	2.32E+09



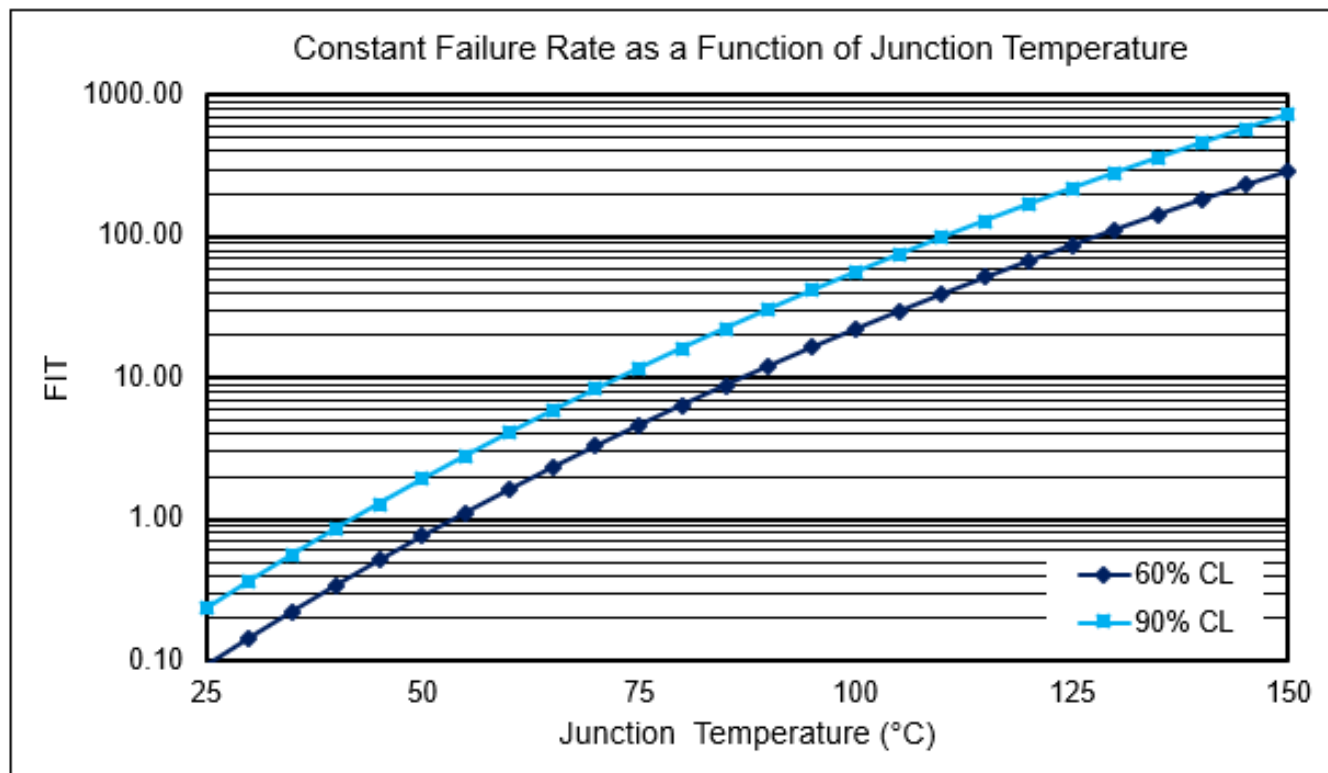
UltraCMOS[®] 3.5 Process Technology

Generation : 350 nm CMOS Silicon Epi Process (U350E)

Units Tested : 8,770

Product Family : DSA, DTC, Switch

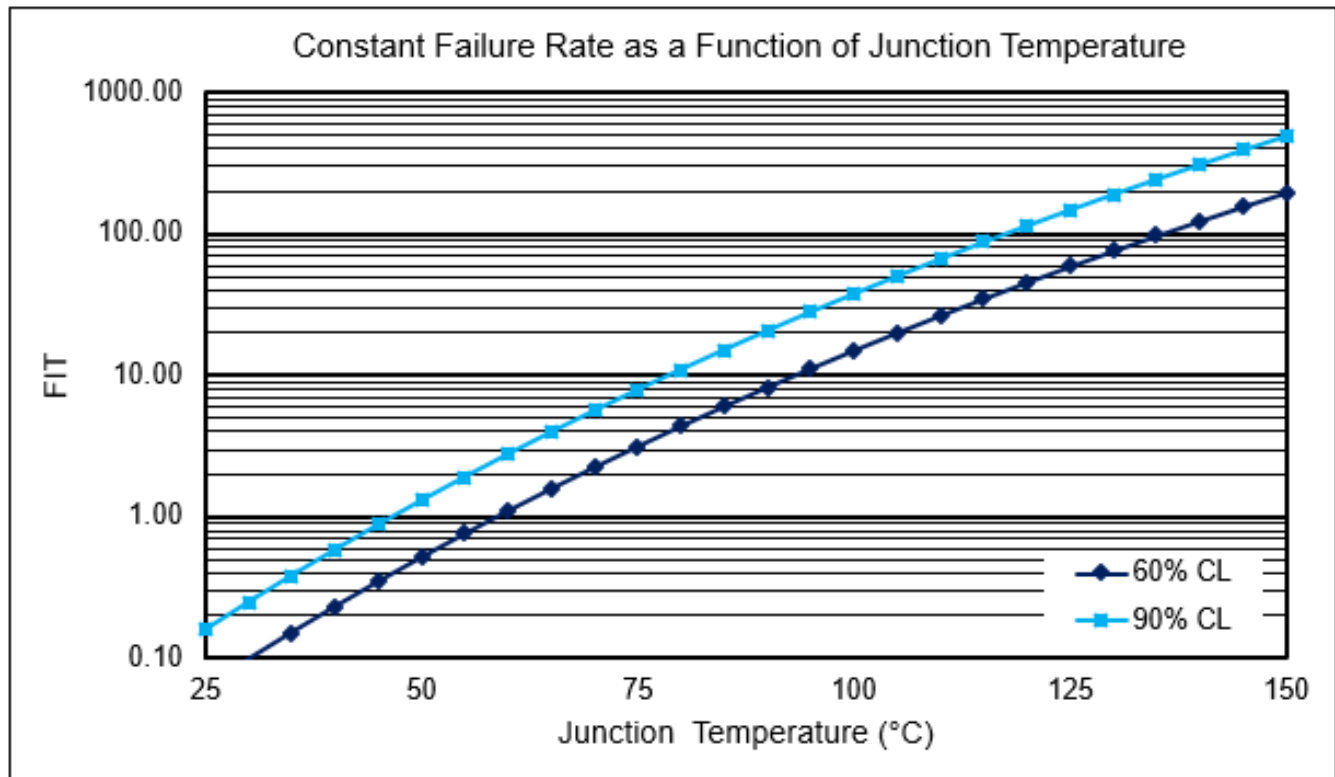
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.07E+08	8.5	1.17E+08
Constant (Random)	8.20E+08	1.1	8.95E+08



UltraCMOS[®] 5 Process Technology

Generation : 350 nm CMOS Bonded Silicon Process (U350B)
 Units Tested : 9,338
 Product Family : DSA, DTC, LMTR, MPAC, PLL, PSH, Switch

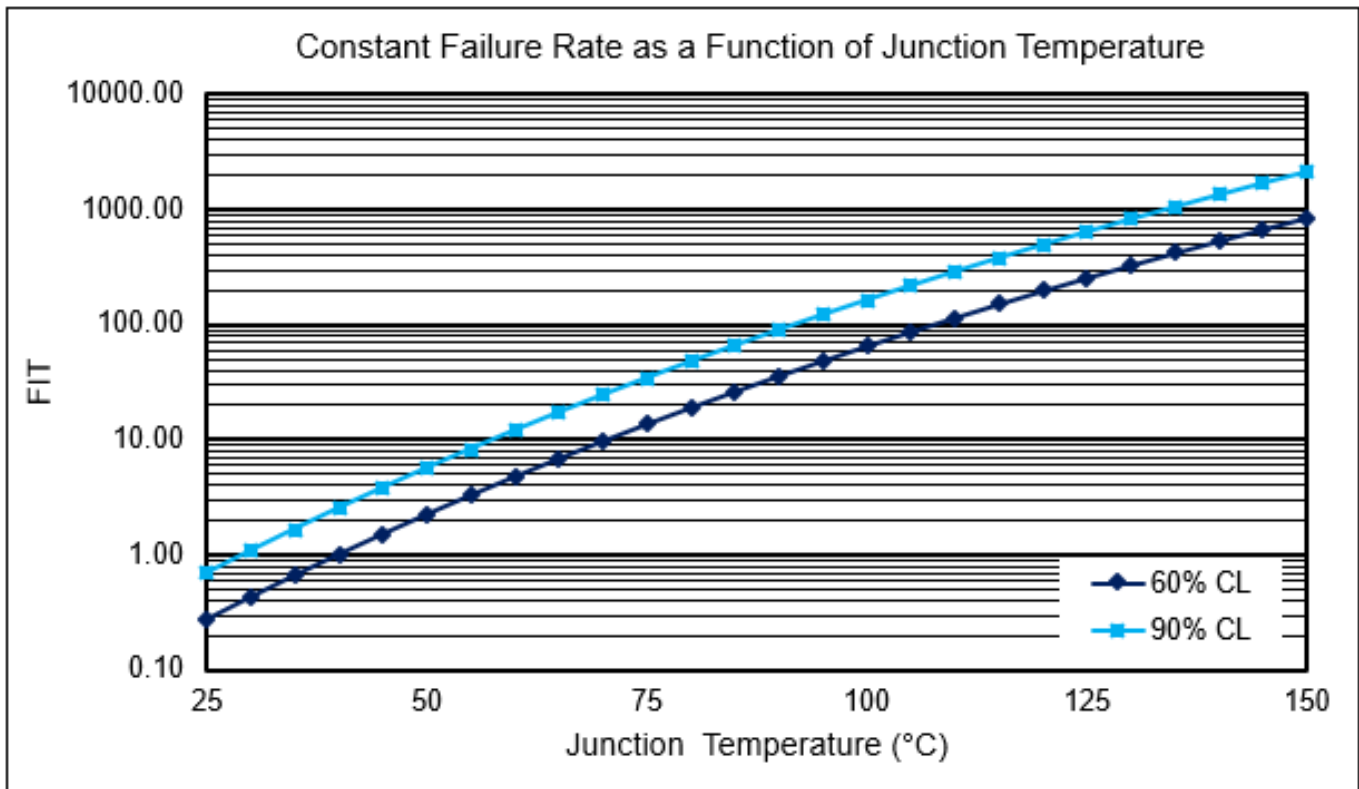
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.15E+08	8.0	1.25E+08
Constant (Random)	1.20E+09	0.8	1.31E+09



UltraCMOS[®] 6 Process Technology

Generation : 250 nm CMOS Silicon Epi Process (U250E2)
 Units Tested : 2,198
 Product Family : Switch

	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life Failure Rate	2.70E+07	33.9	2.95E+07
Constant (Random) Failure Rate	2.78E+08	3.3	3.03E+08



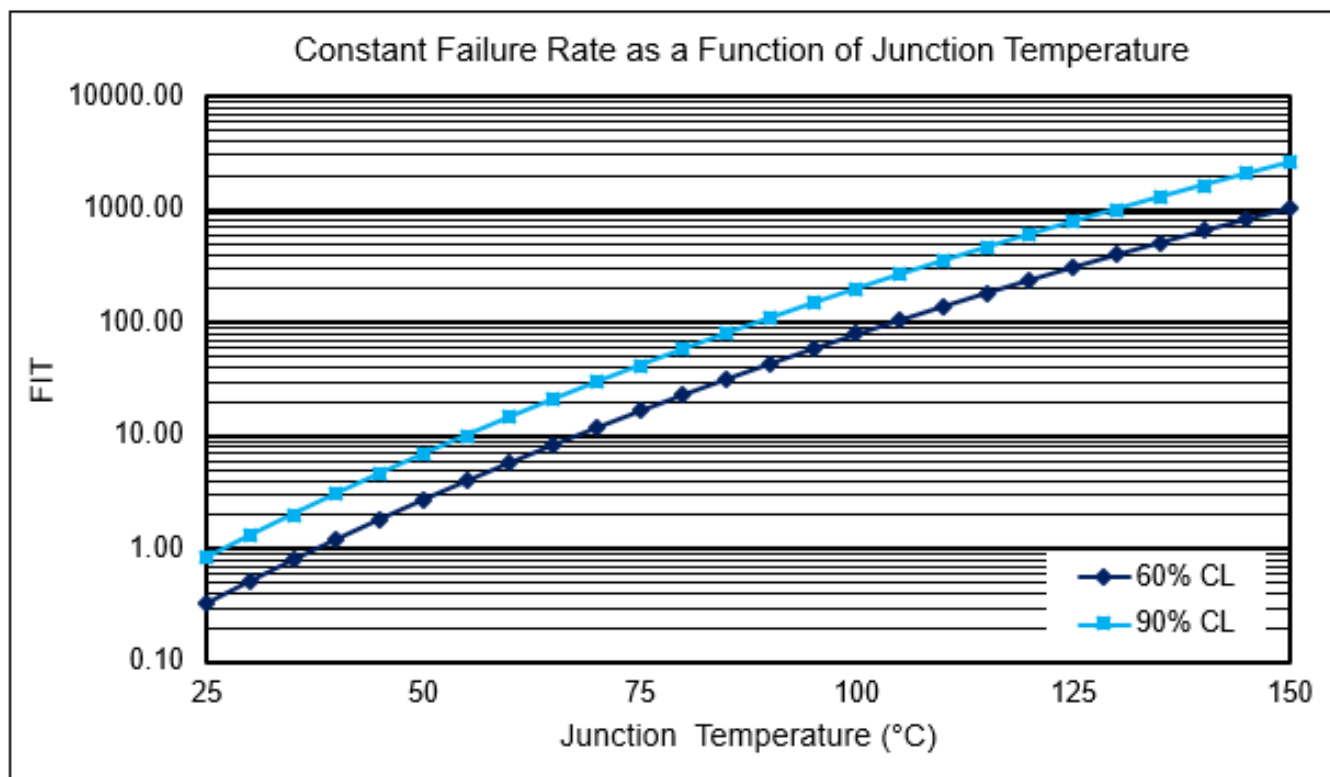
UltraCMOS[®] 6.5 Process Technology

Generation : 250 nm CMOS Silicon Epi Process (U250E4)

Units Tested : 1,831

Product Family : Driver, DSA, Switch

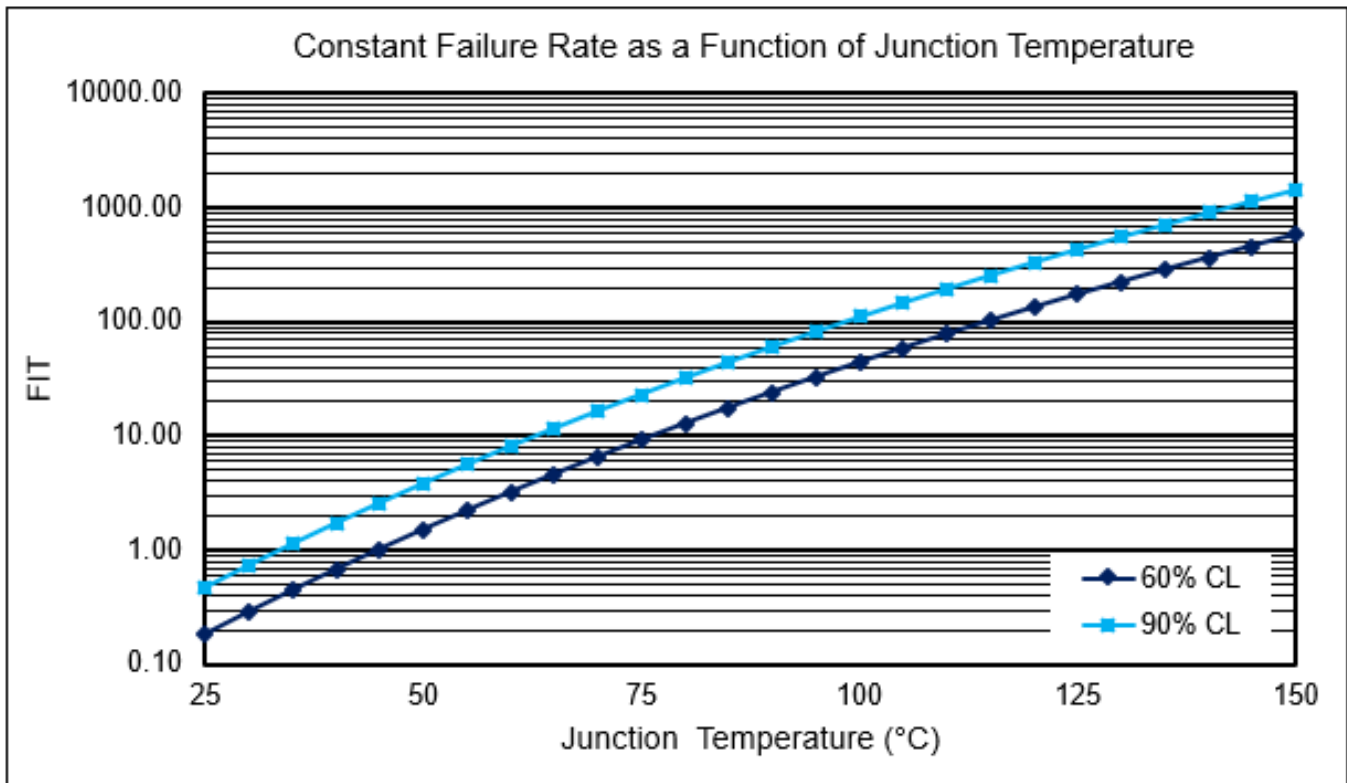
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.83E+07	49.9	2.00E+07
Constant (Random)	2.29E+08	4.0	2.50E+08



UltraCMOS[®] 8 Process Technology

Generation : 250 nm CMOS Bonded Silicon Process (U250B)
 Units Tested : 3,215
 Product Family : Driver, DSA, DTC, LMTR, MPAC, MXR, PSR, Switch

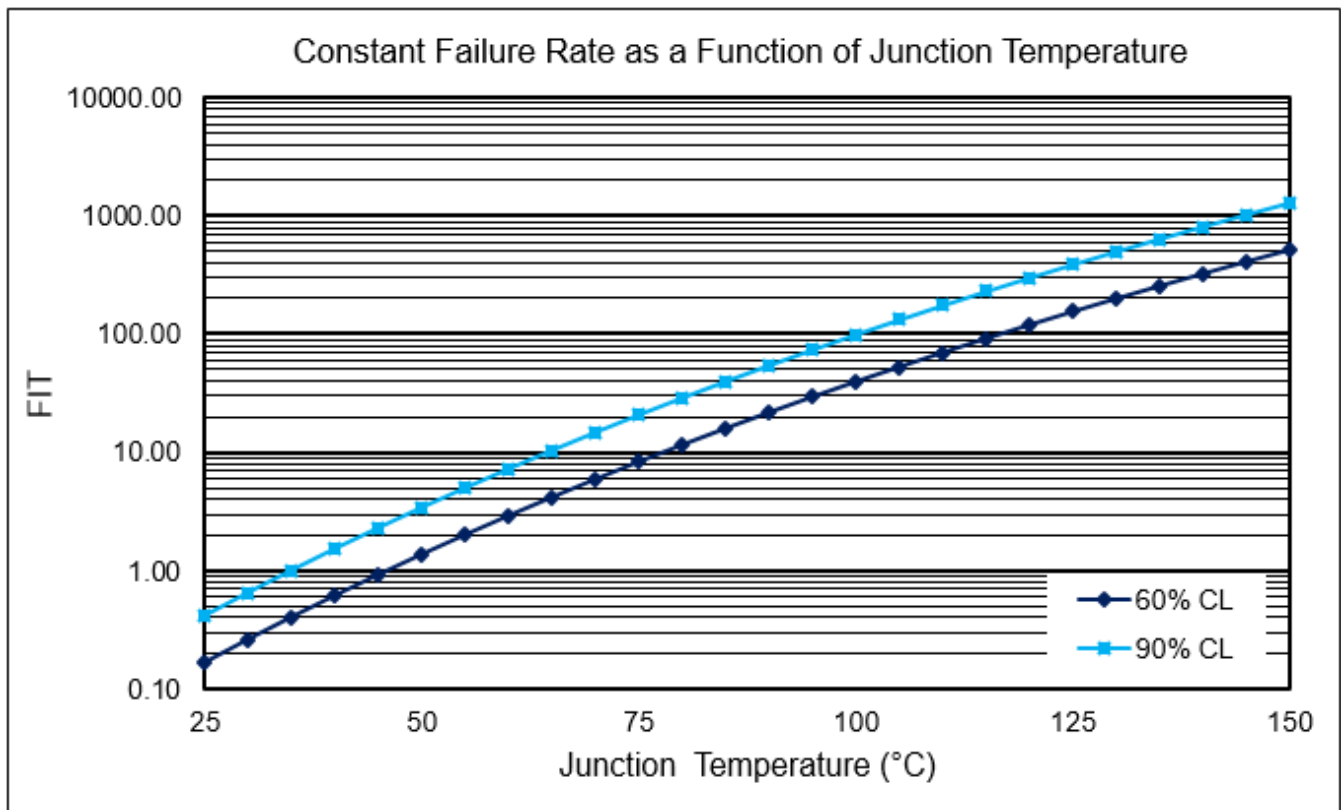
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	3.80E+07	24.1	4.15E+07
Constant (Random)	4.12E+08	2.2	4.50E+08



UltraCMOS[®] 10 Process Technology

Generation : 130nm CMOS Silicon-On-Insulator in 200mm wafer(U130S1)
 Units Tested : 3,806
 Product Family : Switch

	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life	4.06E+07	22.5	4.44E+07
Constant (Random)	4.59E+08	2.0	5.01E+08



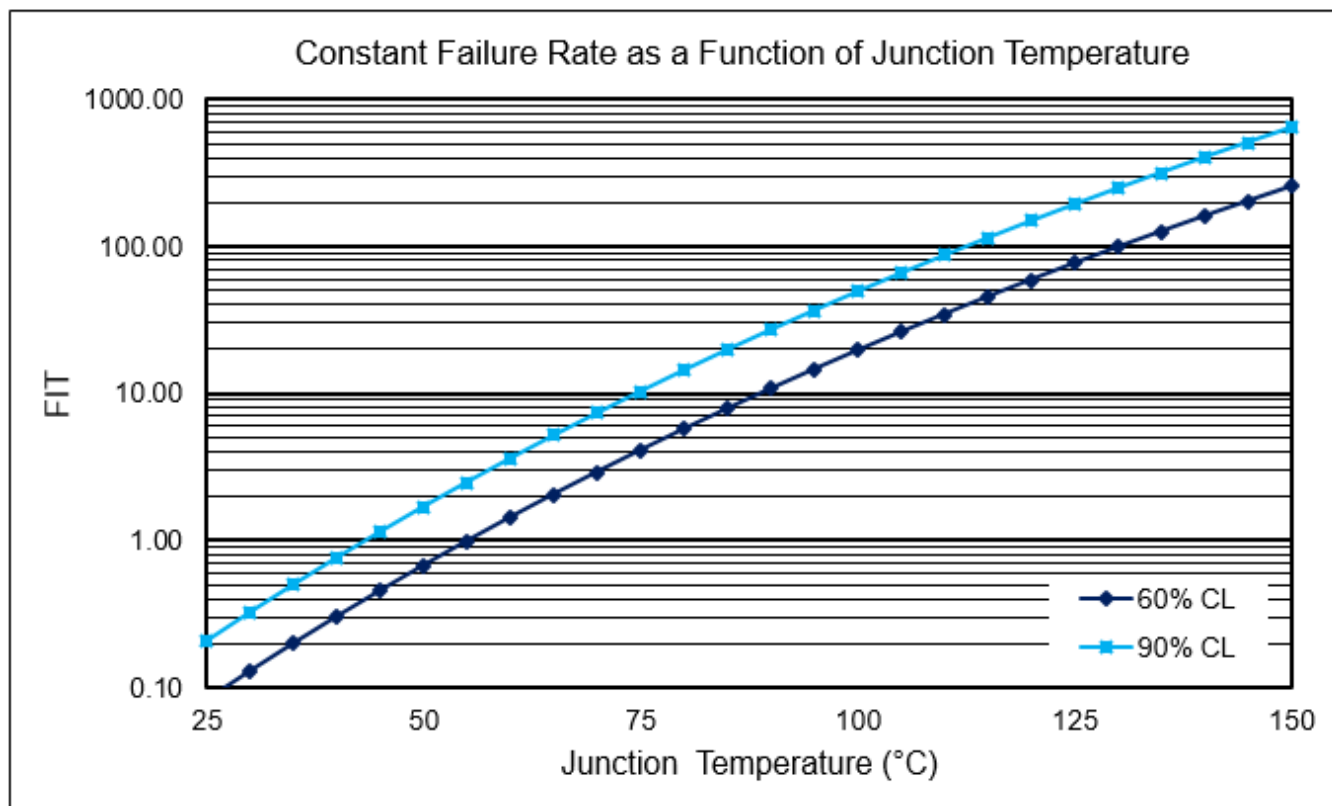
UltraCMOS[®] 11 Process Technology

Generation : 130nm CMOS Silicon-On-Insulator in 300mm wafer (U130S2)

Units Tested : 12,583

Product Family : Amplifier, DC-DC, Switch

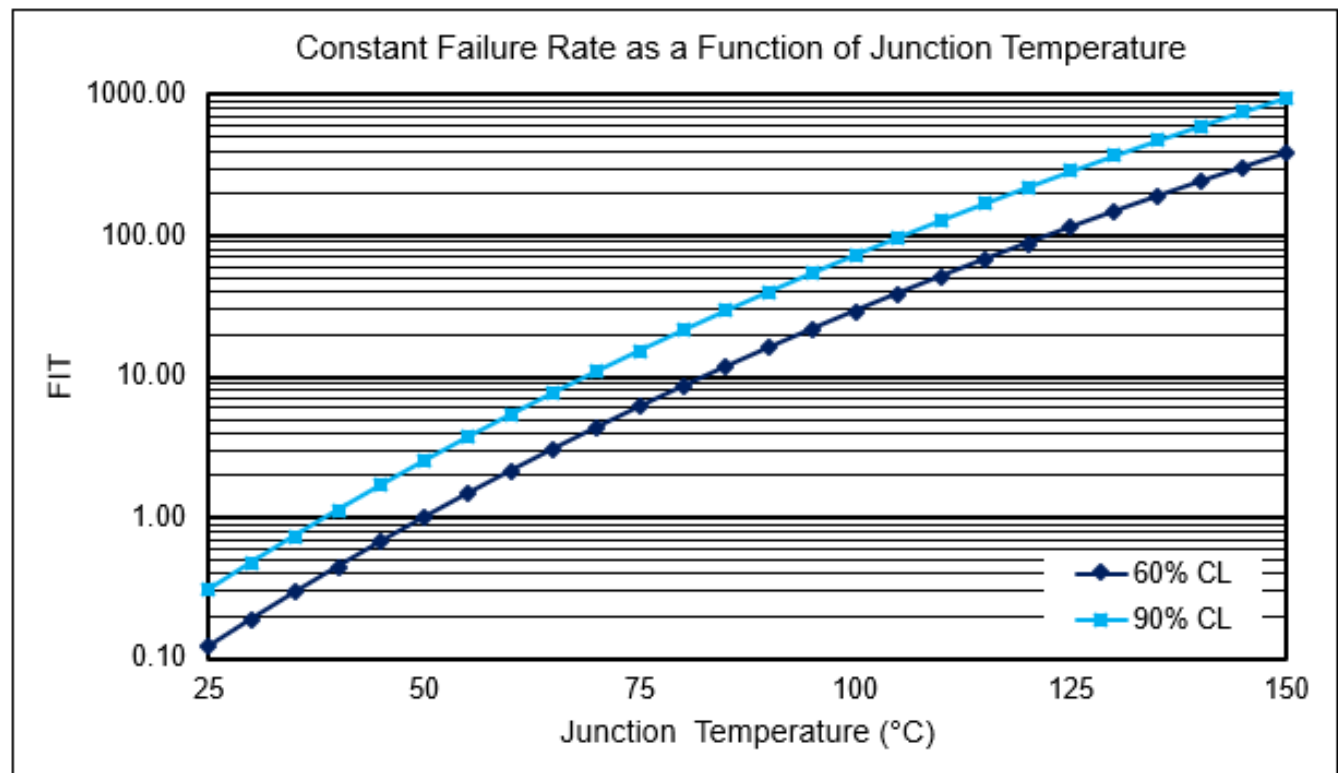
	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life	7.39E+07	12.4	8.07E+07
Constant (Random)	9.29E+08	1.0	1.01E+09



UltraCMOS[®] 12 Process Technology

Generation : 65nm CMOS Silicon-On-Insulator in 300mm wafer (U130S3)
 Units Tested : 15,273
 Product Family : Amplifier, DSA, PAC, Switch

	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life Failure	7.94E+07	11.5	8.66E+07
Constant (Random)	6.23E+08	1.5	6.80E+08



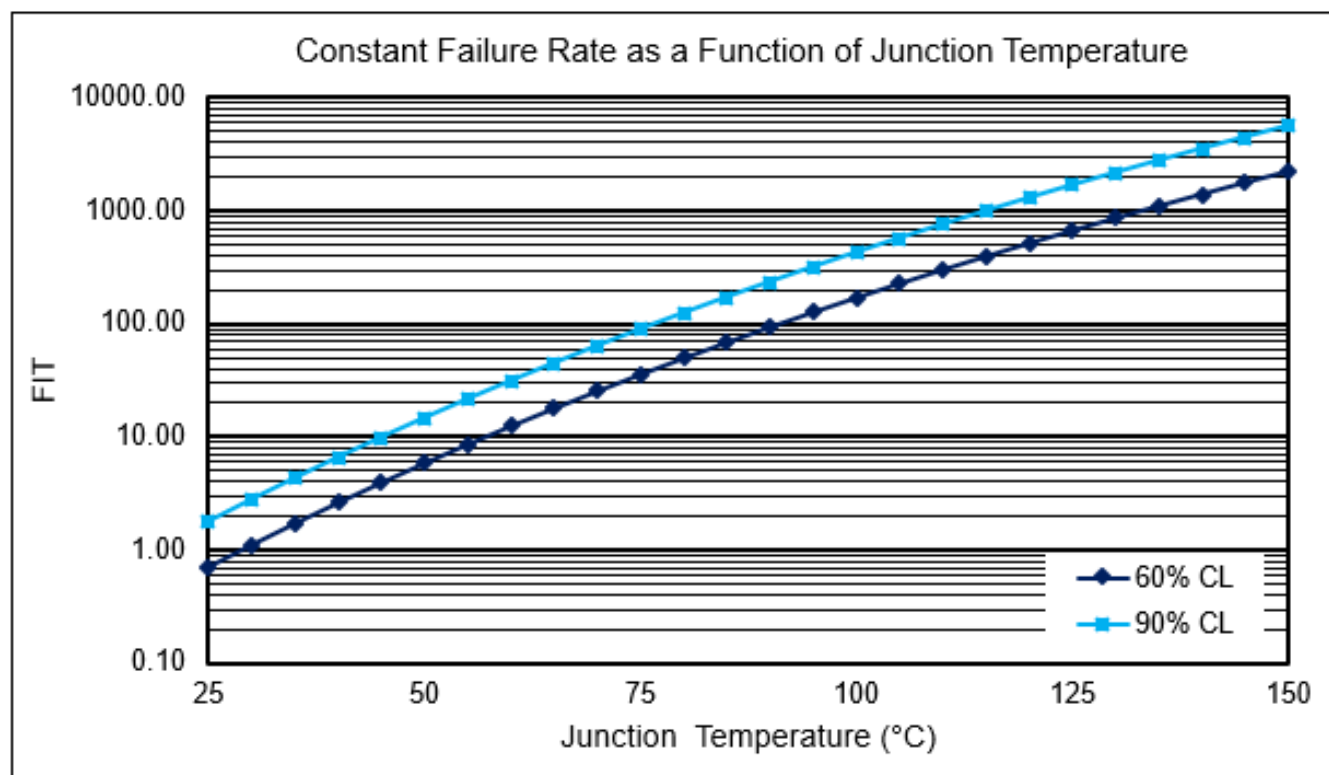
UltraCMOS[®] 12A Process Technology

Generation : 65nm CMOS Silicon-On-Insulator in 300mm wafer (U130S4)

Units Tested : 3,291

Product Family : Amplifier

	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life Failure	1.22E+07	74.8	1.34E+07
Constant (Random)	1.07E+08	8.6	1.16E+08



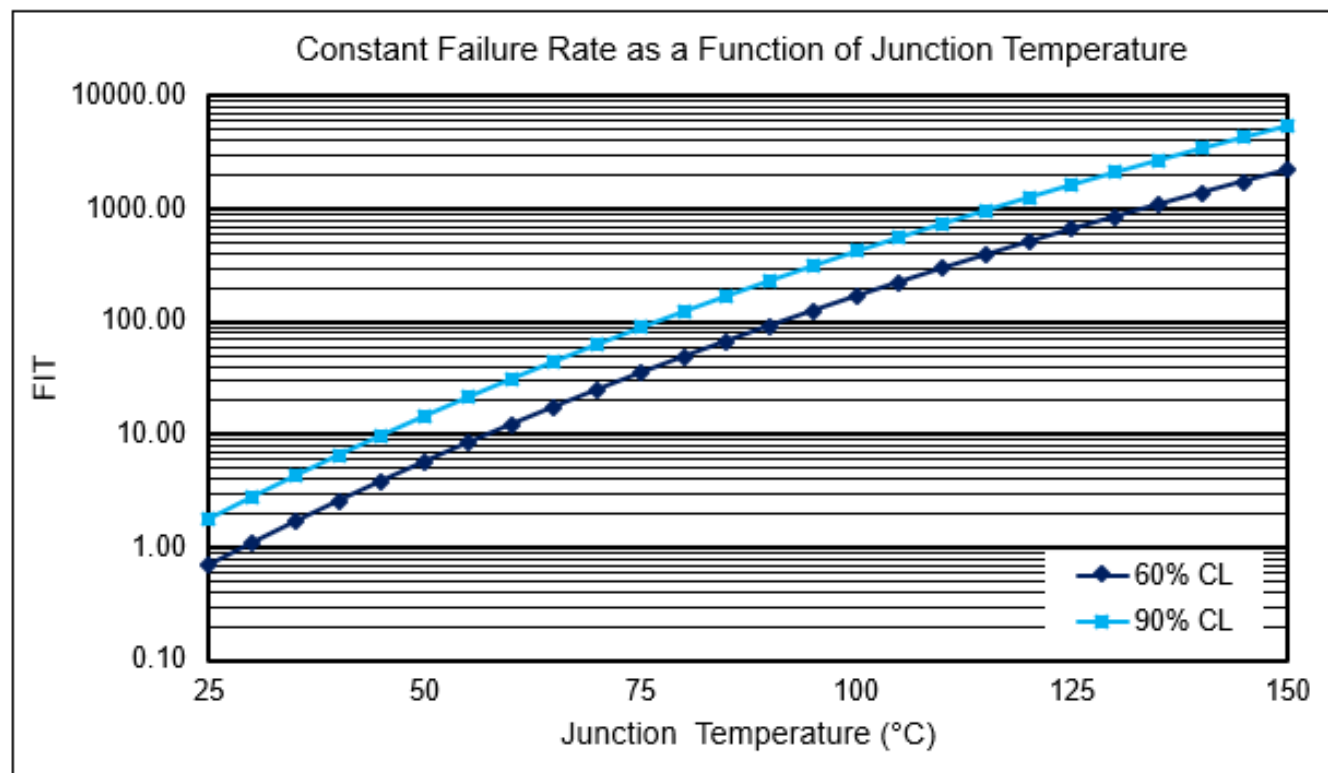
UltraCMOS[®] 13 Process Technology

Generation : 65nm CMOS Silicon-On-Insulator in 300mm wafer (U130S4)

Units Tested : 4,364

Product Family : Amplifier, Switch

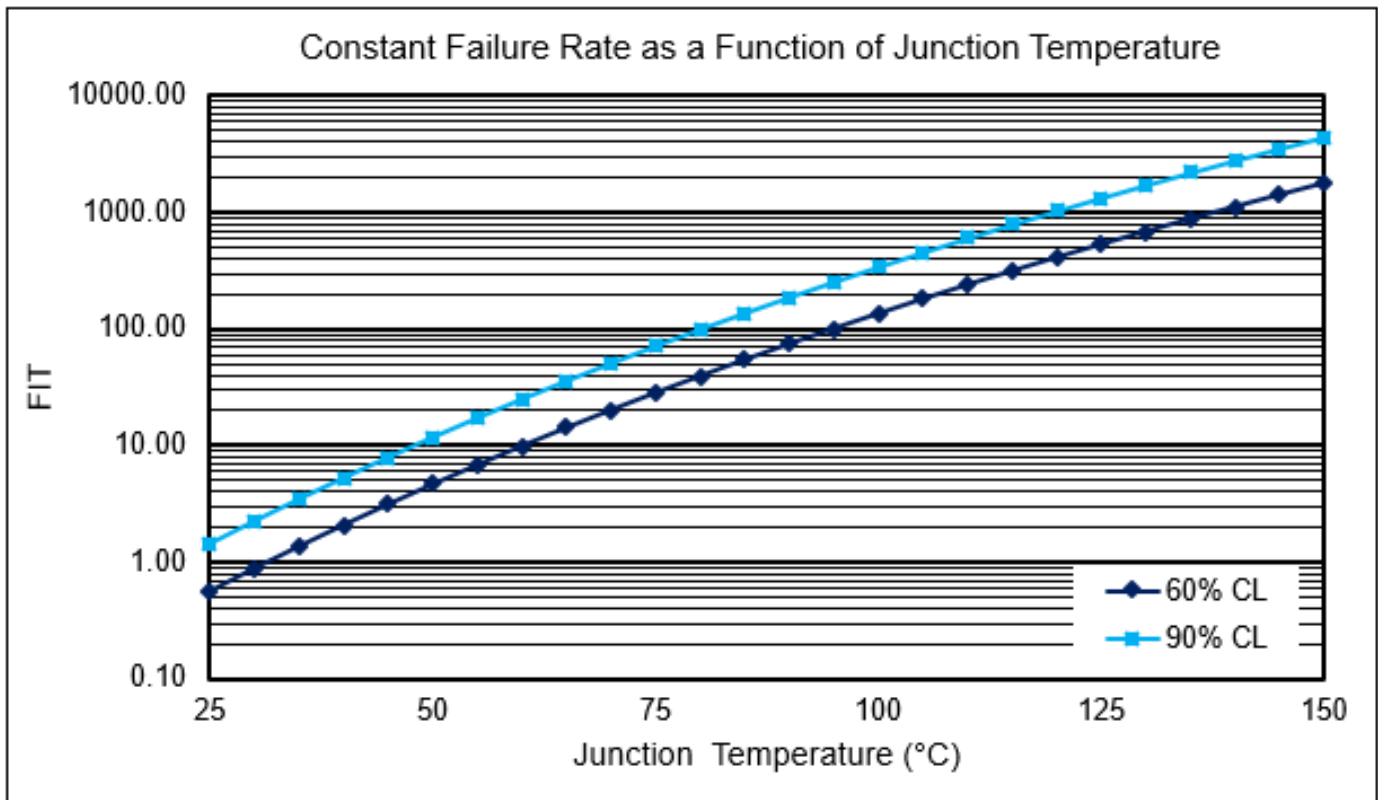
	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life Failure	1.62E+07	56.4	1.77E+07
Constant (Random)	1.08E+08	8.5	1.18E+08



UltraCMOS[®] 13S Process Technology

Generation : 65nm CMOS Silicon-On-Insulator in 300mm wafer (U130S4)
 Units Tested : 8,559
 Product Family : Switch

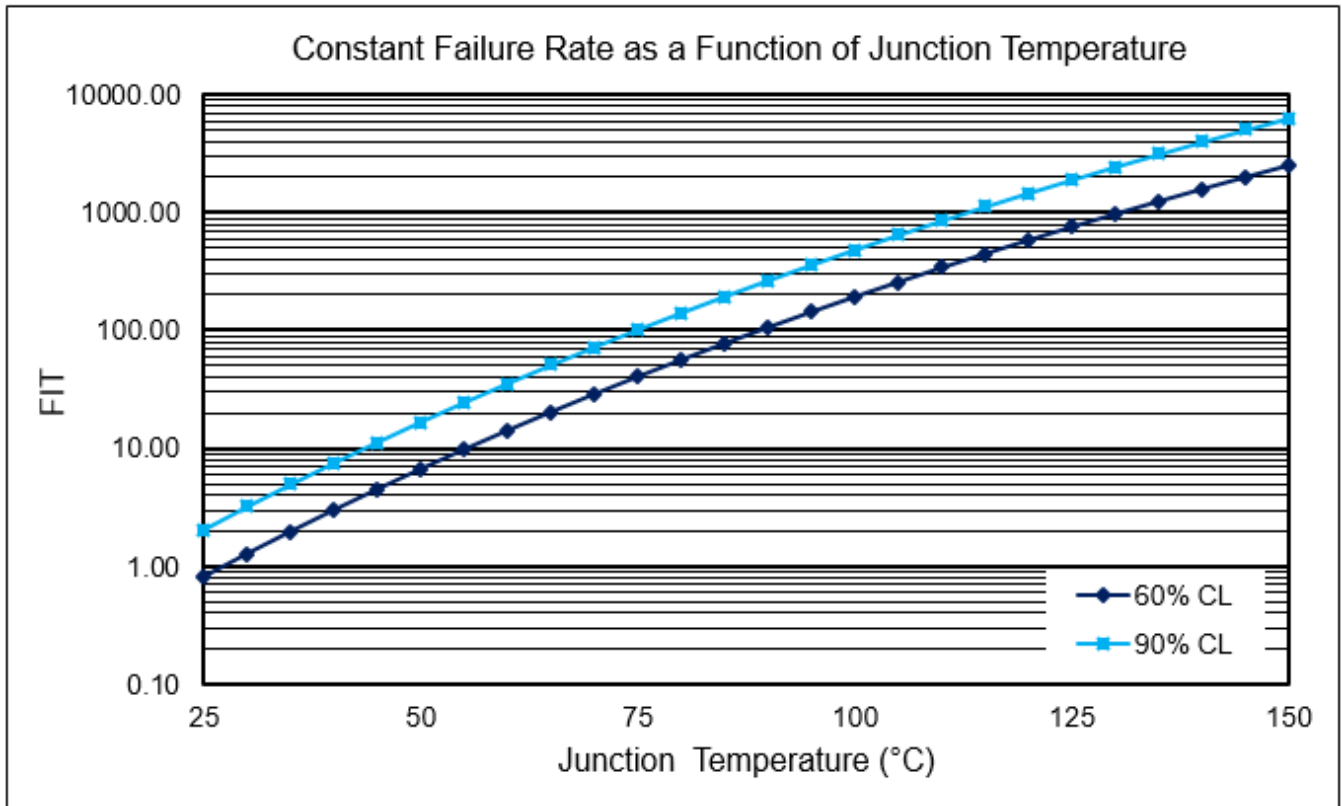
	Standard Failure Rate Calculations at 55°C and 60% CL		
	EDH (hours)	FITs	MTTF (hours)
Early Life Failure	3.08E+07	29.8	3.36E+07
Constant (Random)	1.34E+08	6.8	1.46E+08



BCD GEN II Process Technology

Generation : 180nm BCD Gen 2 Process
 Units Tested : 1,207
 Product Family : DC-DC

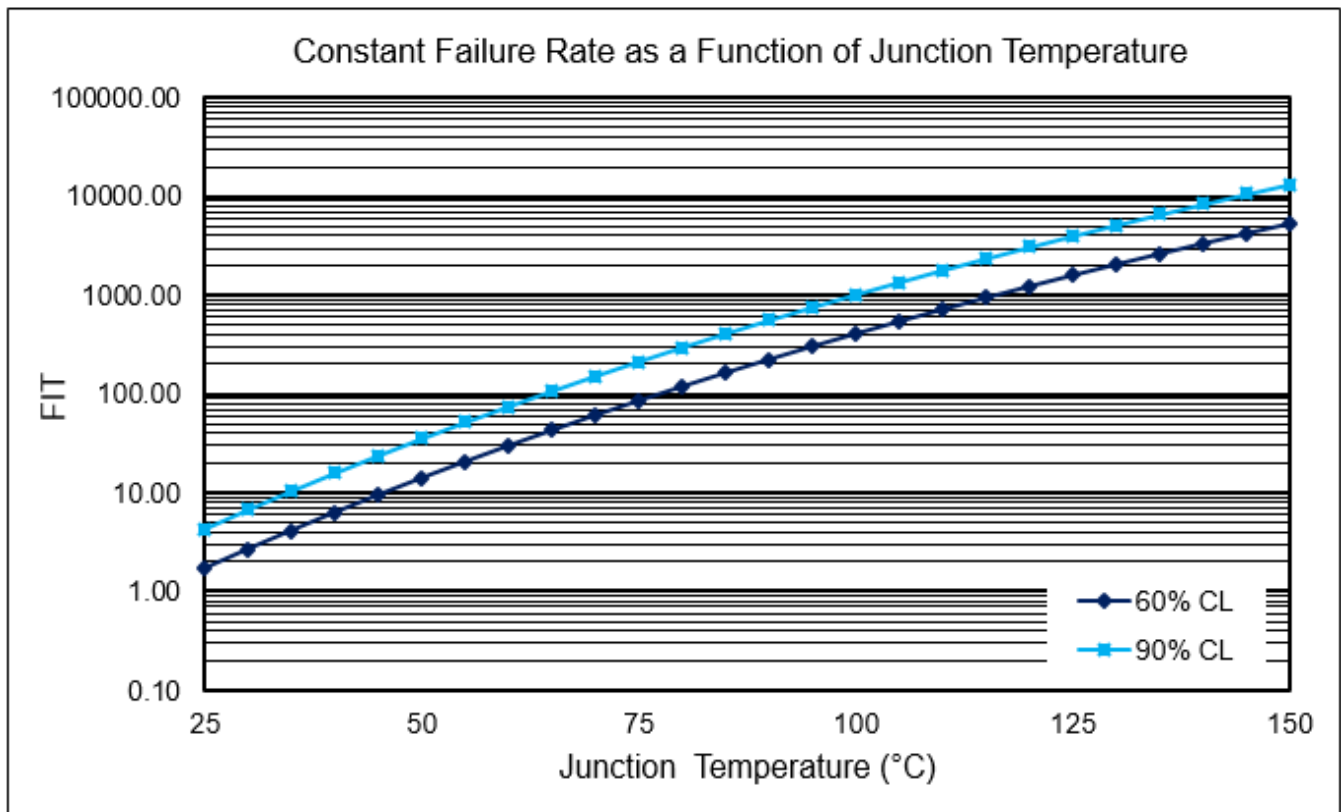
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	4.49E+06	204.0	4.90E+06
Constant (Random)	9.36E+07	9.8	1.02E+08



BCDLite Process Technology

Generation : 130nm BCDLite Process
 Units Tested : 510
 Product Family : DC-DC

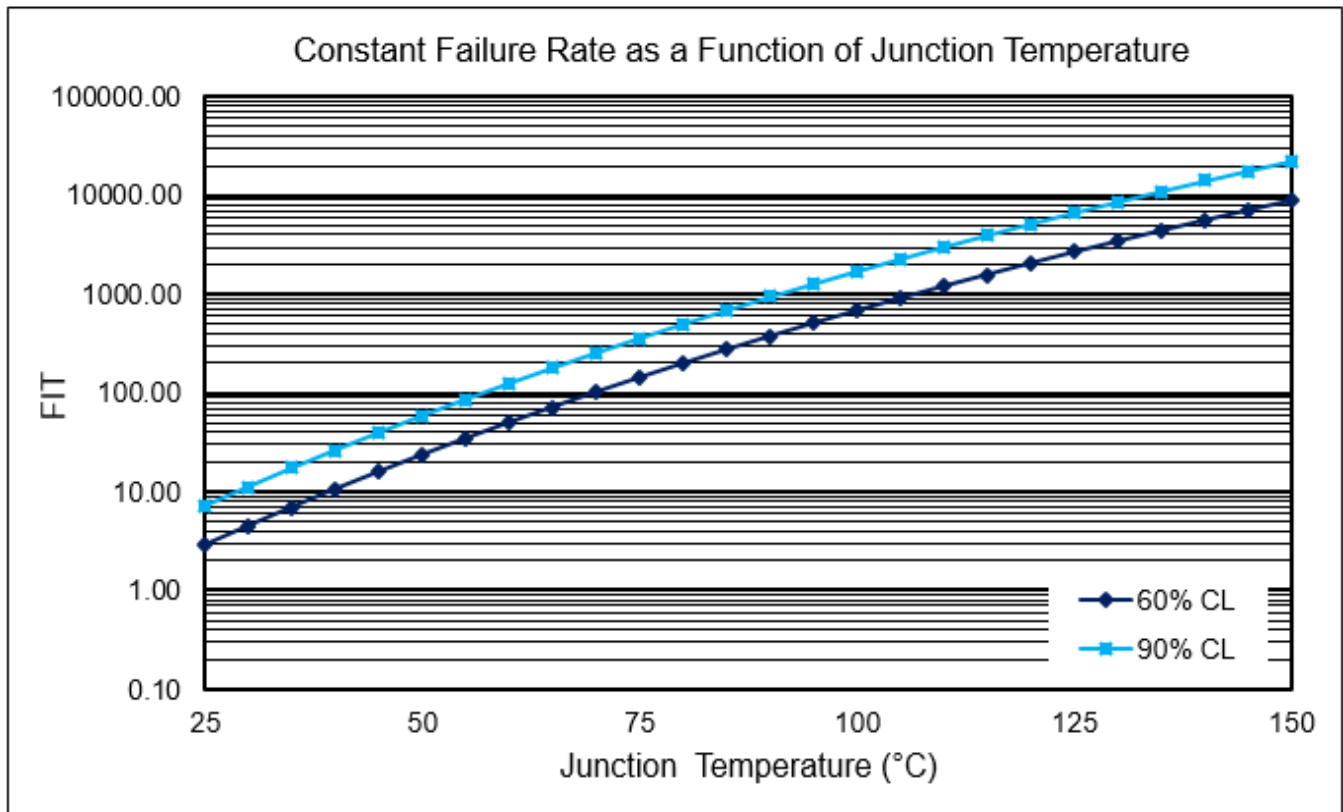
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	3.80E+06	241.4	4.14E+06
Constant (Random)	4.45E+07	20.6	4.86E+07



55LPx Process Technology

Generation : 55nm 300mm wafer (C055C1E6)
 Units Tested : 343
 Product Family : ASIC

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	3.80E+06	241.4	4.14E+06
Constant (Random)	4.45E+07	20.6	4.86E+07





Product Family Classification

Amplifiers (LNA & PA)

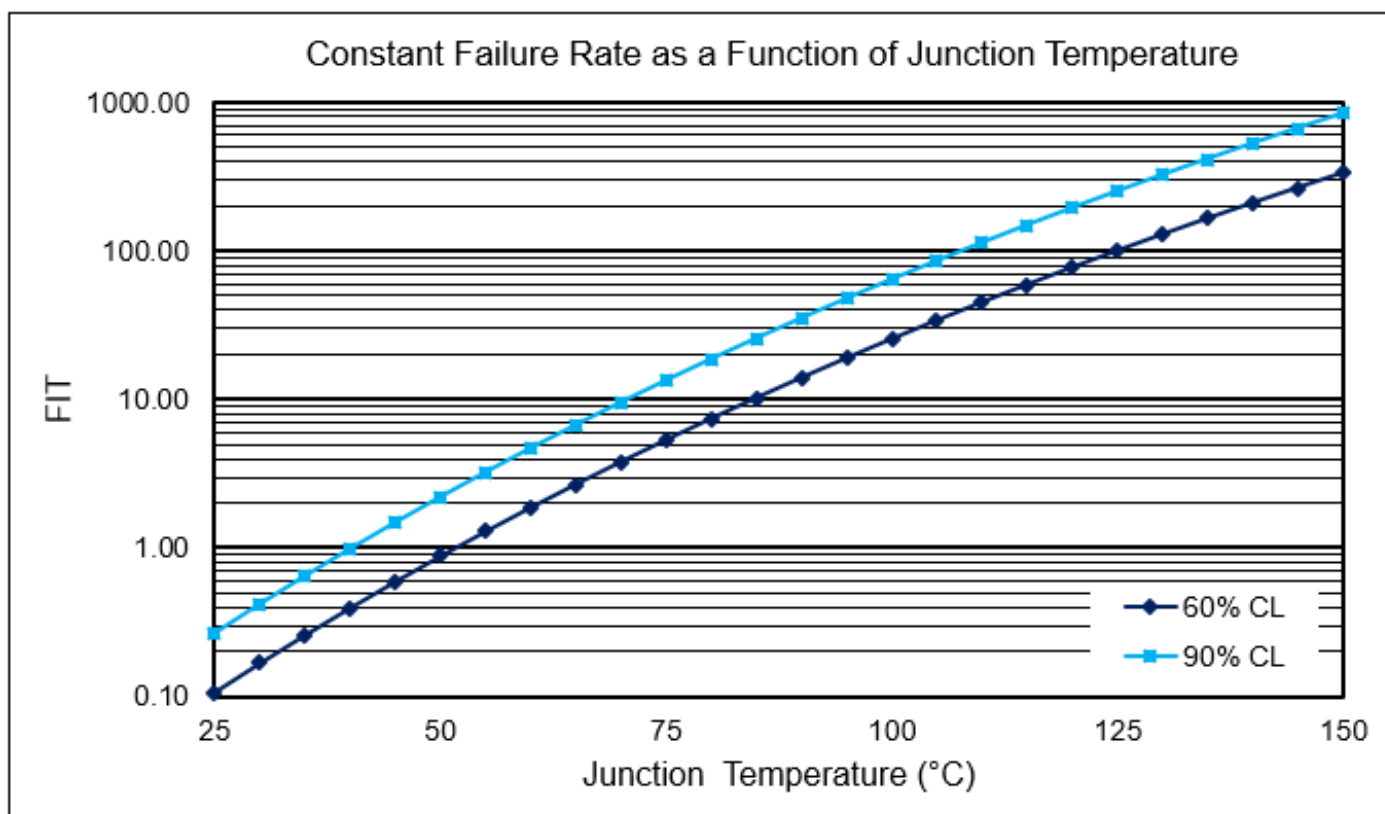
Description : UltraCMOS Low-Noise Amplifiers (LNA) and Power Amplifiers (PA)

Products in Family : PE47002x, PE47004x, PE470681, PE471110, PE471112, PE471741, PE472110, PE477180, PE477181, PE478021, PE478031, PE478051, PE478070, PE478090, PE478091, PE478100, PE478110, PE478130, PE47814x, PE47901x, PE47902x, PE479050, PE479070, PE479081, PE479091, PE479381, PE521200, PE521221, PE523211, PE53210

Process Technology : UltraCMOS[®] 11, UltraCMOS[®] 12, UltraCMOS[®] 12A, UltraCMOS[®] 13

Units Tested : 19,702

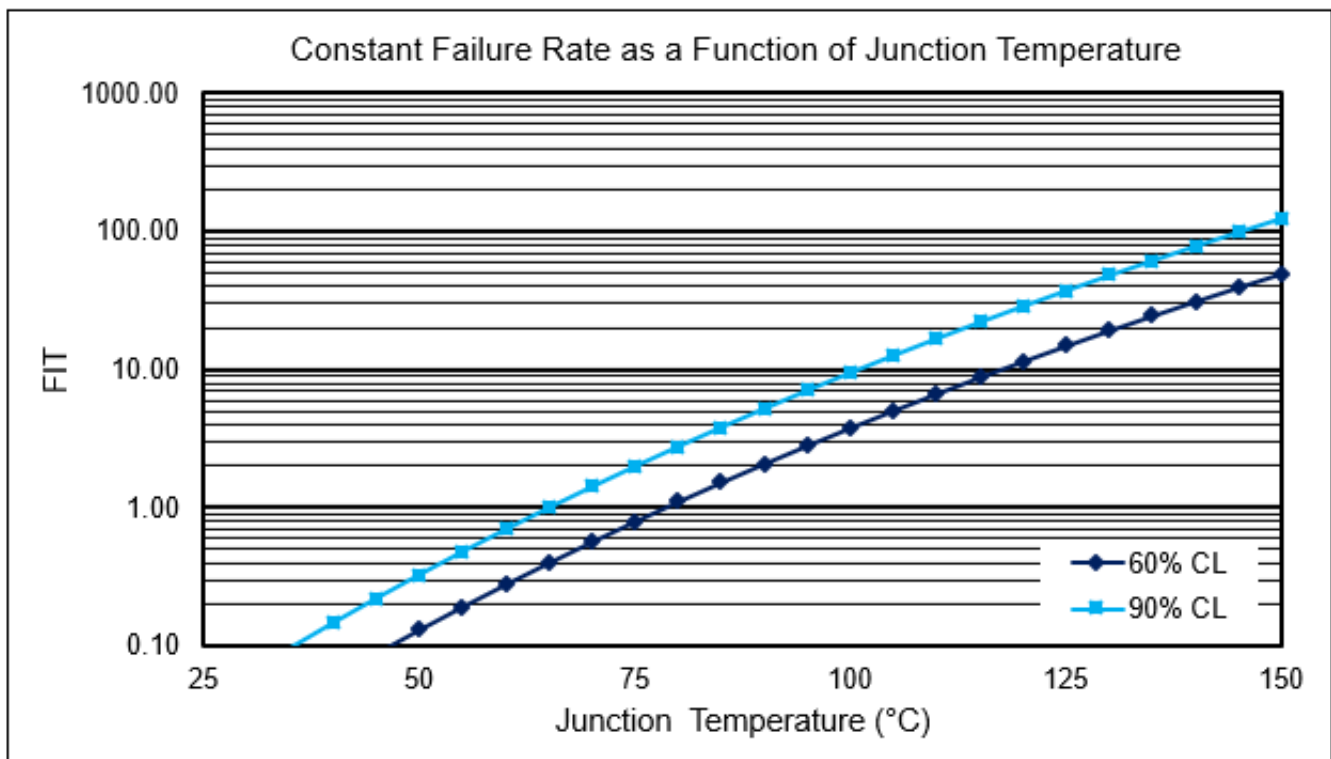
		Standard Failure Rate Calculations at 55°C and 60% CL		
		EDH (hours)	FITs	MTTF (hours)
Early Life		7.85E+07	11.7	8.56E+07
Constant (Random)		7.10E+08	1.3	7.75E+08



Switches (ASW, HPSW, ATS & BSW)

- Description : Multi-pole & multi-throw high power handling antenna switch products for Mobile Wireless RF, broadband infrastructure, and Test Equipment /ATE applications.
- Products in Family : See Appendix A (page 43)
- Process Technology : UltraCMOS[®] 2, UltraCMOS[®] 3.5, UltraCMOS[®] 5, UltraCMOS[®] 6, UltraCMOS[®] 6.5, UltraCMOS[®] 8, UltraCMOS[®] 10, UltraCMOS[®] 11, UltraCMOS[®] 12, UltraCMOS[®] 13, UltraCMOS[®] 13S
- Units Tested : 55,357

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	5.53E+08	1.7	6.03E+08
Constant (Random)	4.76E+09	0.2	5.19E+09



ASIC

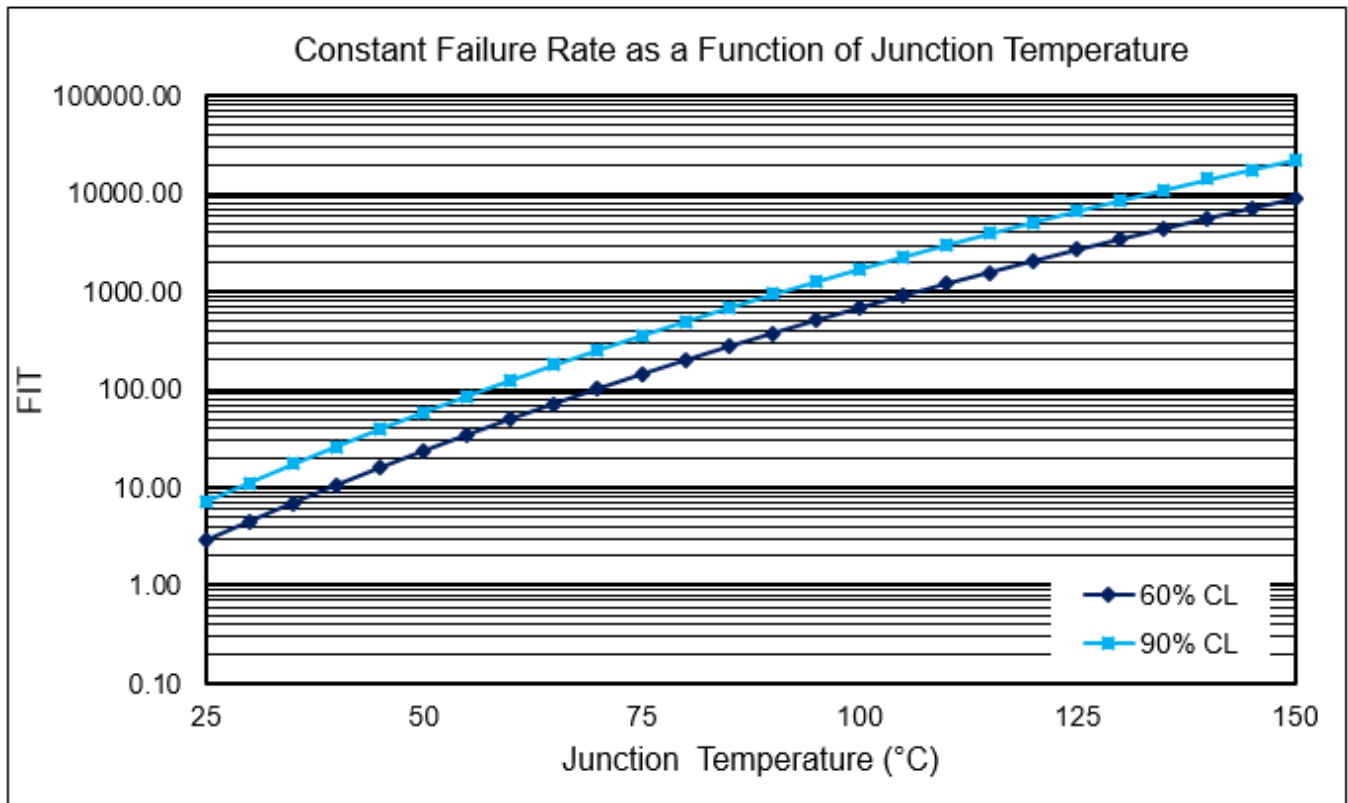
Description : These ICs have high precision ADCs for sensing MEMS capacitance and high accuracy temperature sensors to support high conversion rates and low latency.

Products in Family : WP71900, WP71901

Process Technology : 55LPx

Units Tested : 343

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.28E+06	717.7	1.39E+06
Constant (Random)	2.66E+07	34.5	2.90E+07



DC-DC

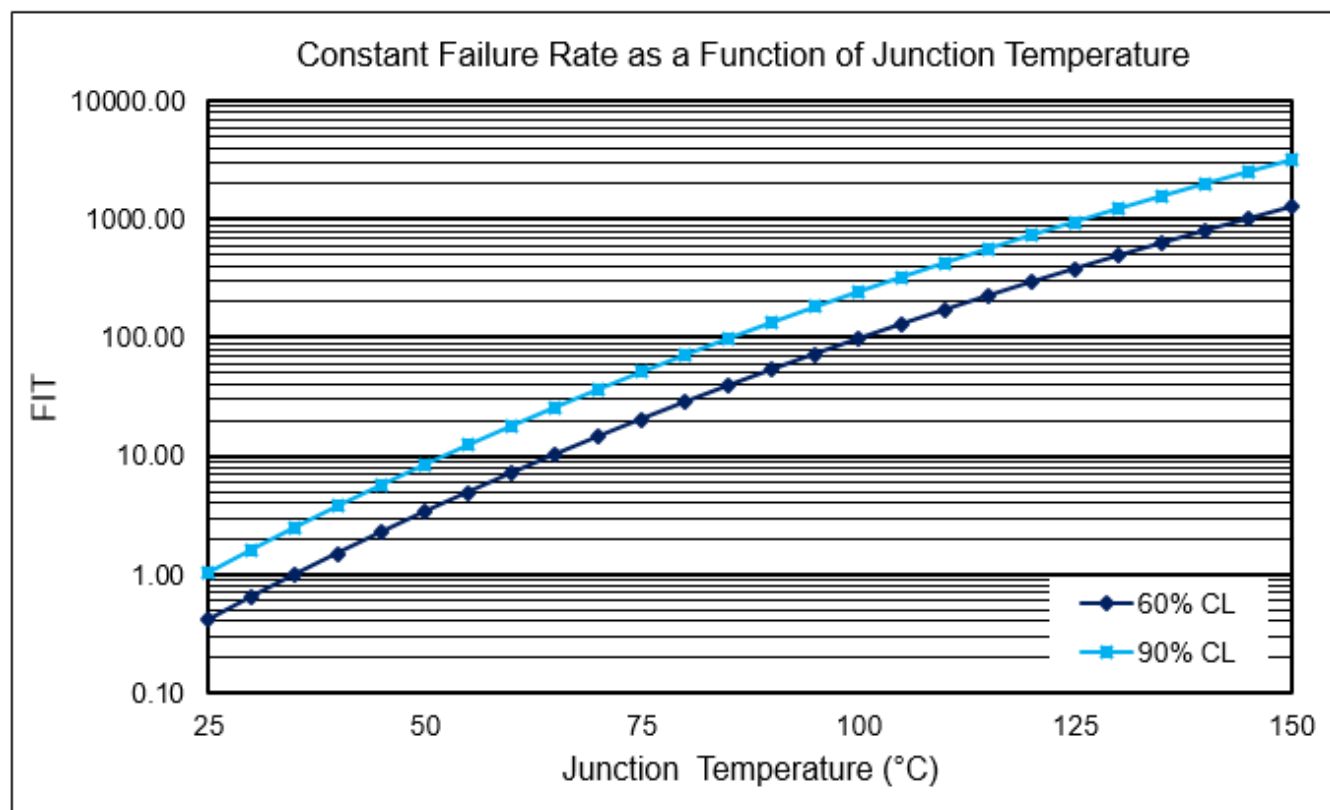
Description : These devices are ultra-high efficiency DC/DC converter solution with integrated programmable current sinks that drive strings of LEDs.

Products in Family : PE22100, PE23100, PE23102, PE23261, PE23363, PE24101, PE24102, PE25200, PE99151, PE99153, PE99153-11, PE99155,

Process Technology : BCD GEN II, BCDLite, UltraCMOS® 2, UltraCMOS® 11

Units Tested : 2,567

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.17E+07	78.6	1.27E+07
Constant (Random)	1.87E+08	4.9	2.04E+08



Digital Step Attenuators (DSA)

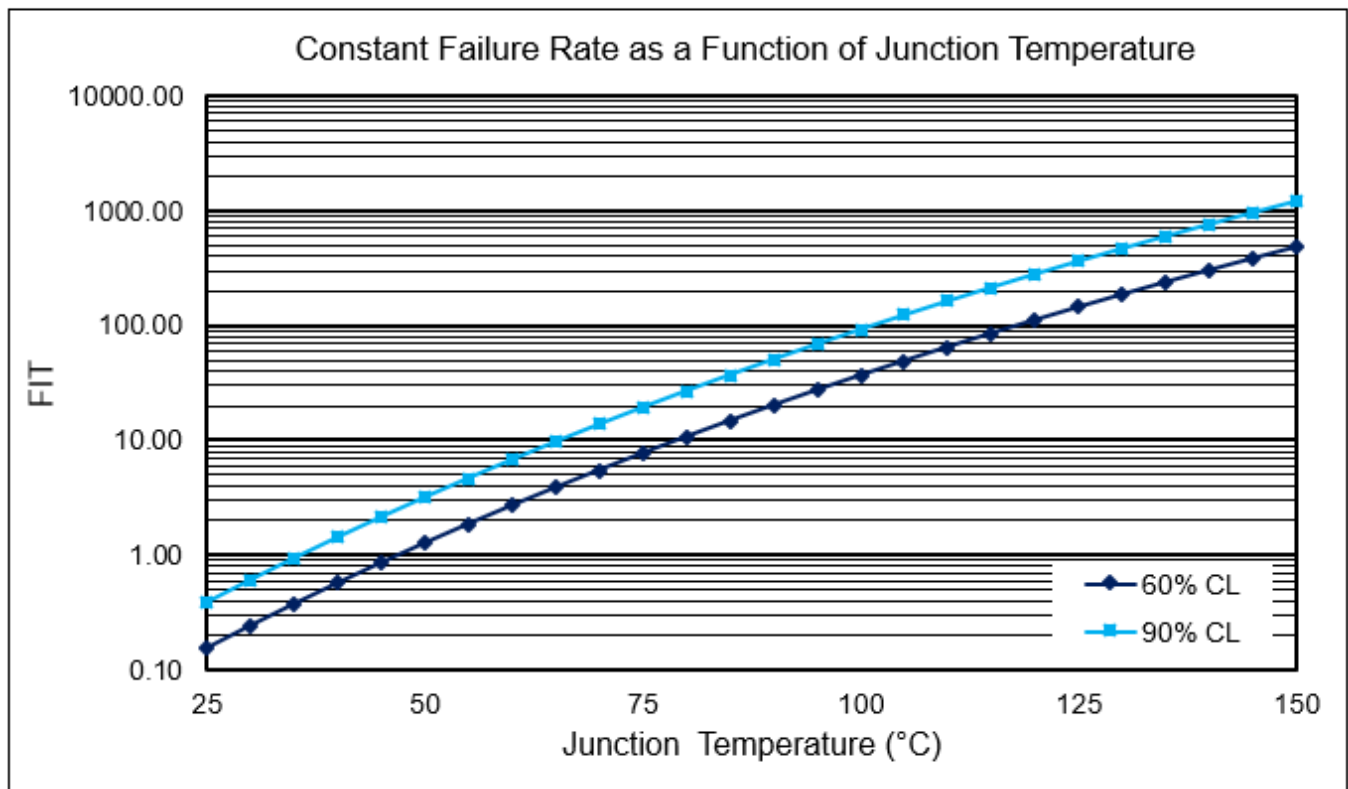
Description : 50Ω and 75Ω Digital Step Attenuators for wireless infrastructure, microwave, test equipment and high reliability space applications.

Products in Family : PE4302, PE4306, PE4308, PE4309, PE4312, PE43204, PE43205, PE43610, PE23614, PE43703, PE43704, PE43713, PE43713, PE94302

Process Technology : UltraCMOS[®] 2, UltraCMOS[®] 3.5, UltraCMOS[®] 5, UltraCMOS[®] 6.5, UltraCMOS[®] 8, UltraCMOS[®] 12

Units Tested : 4,471

		Standard Failure Rate Calculations at 55°C and 60% CL		
		EDH (hours)	FITs	MTTF (hours)
Early Life		4.36E+07	21.0	4.76E+07
Constant (Random)		4.92E+08	1.9	5.37E+08



Digitally Tunable Capacitors (DTC)

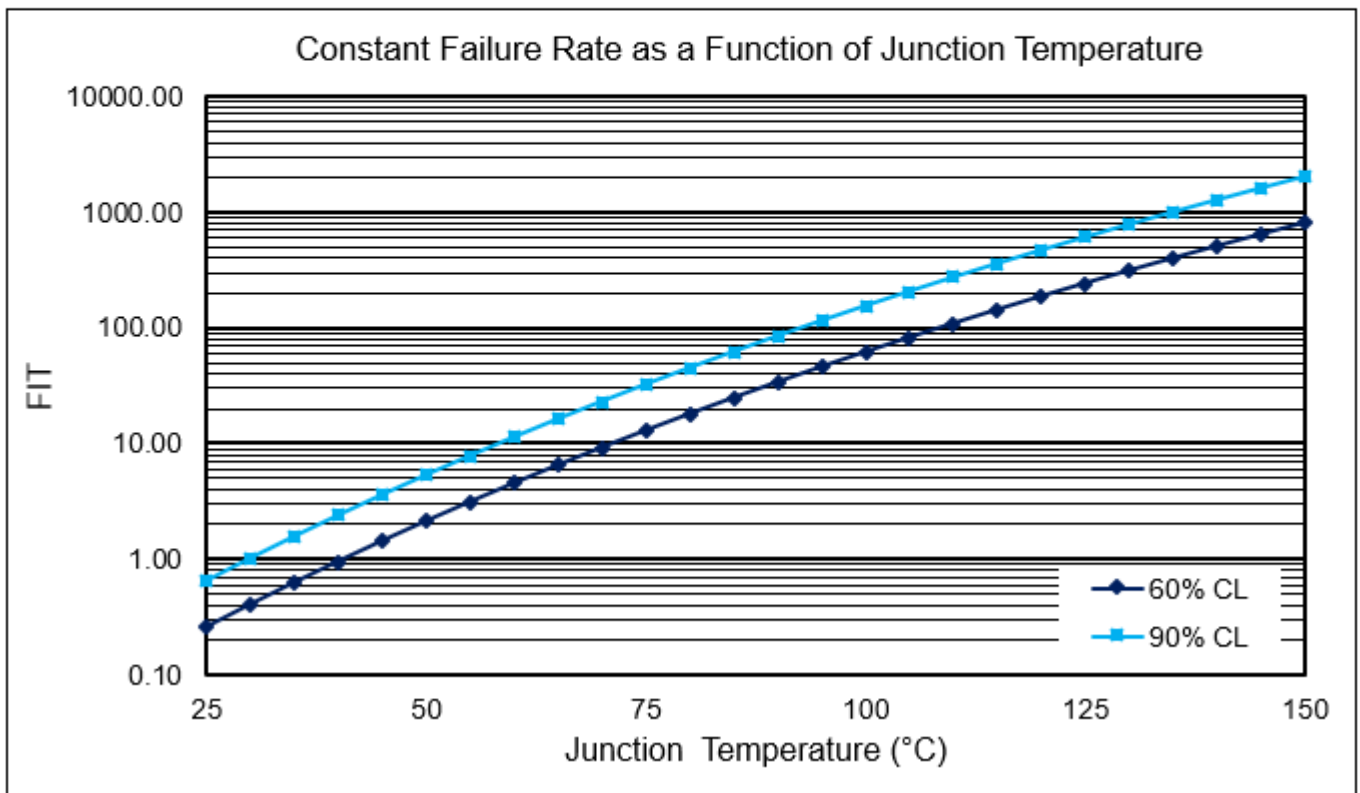
Description : Supports a wide range of tuning applications, from tuning the center frequency of mobile-TV and antennas, to tunable impedance

Products in Family : PE623060, PE623090, PE64102, PE64906, PE62304, PE62305, PE64904, PE613040, PE613050

Process Technology : UltraCMOS® 3.5, UltraCMOS® 5, UltraCMOS® 8

Units Tested : 2,379

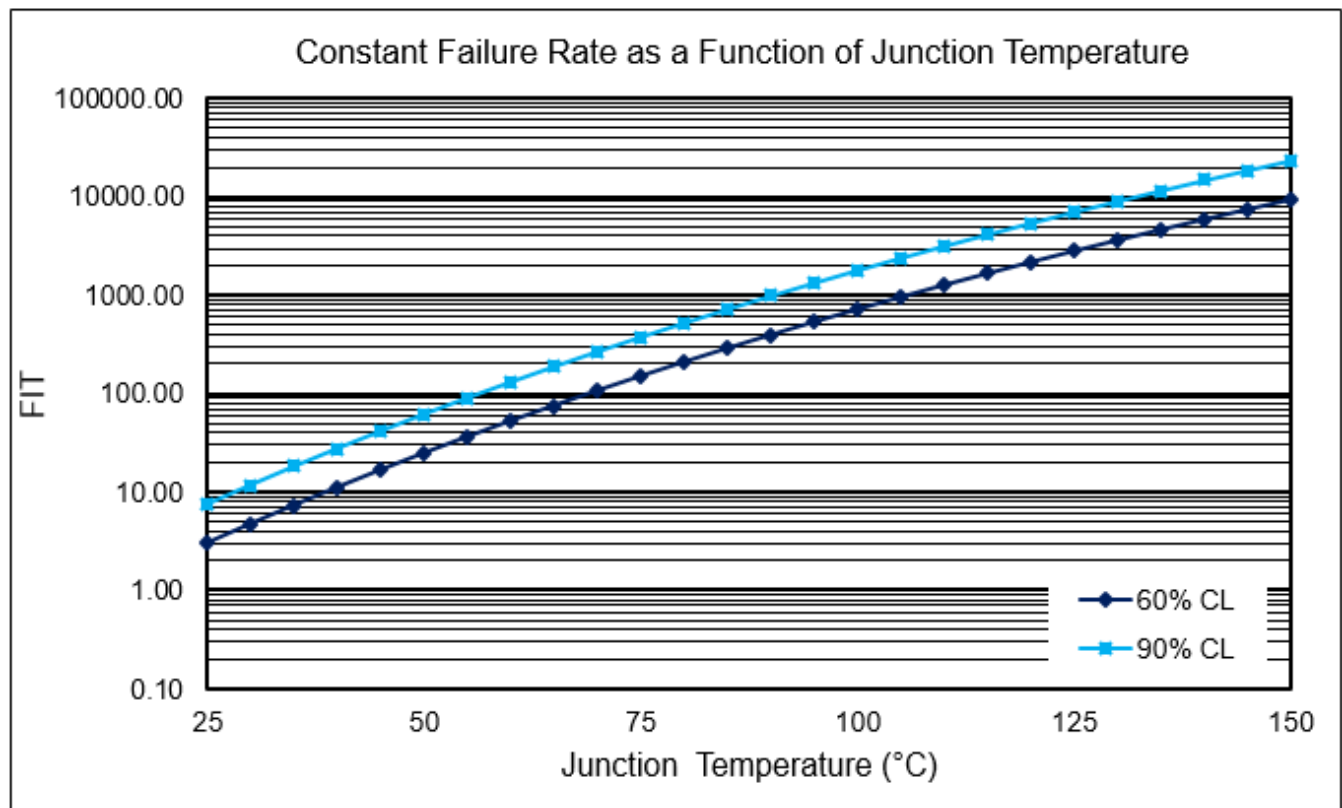
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	2.82E+07	32.5	3.07E+07
Constant (Random)	2.95E+08	3.1	3.22E+08



GaN Driver Product Family

Description : High-speed FET Driver
 Products in Family : PE29100, PE29101, PE29102
 Process Technology : UltraCMOS® 6.5, UltraCMOS® 8
 Units Tested : 327

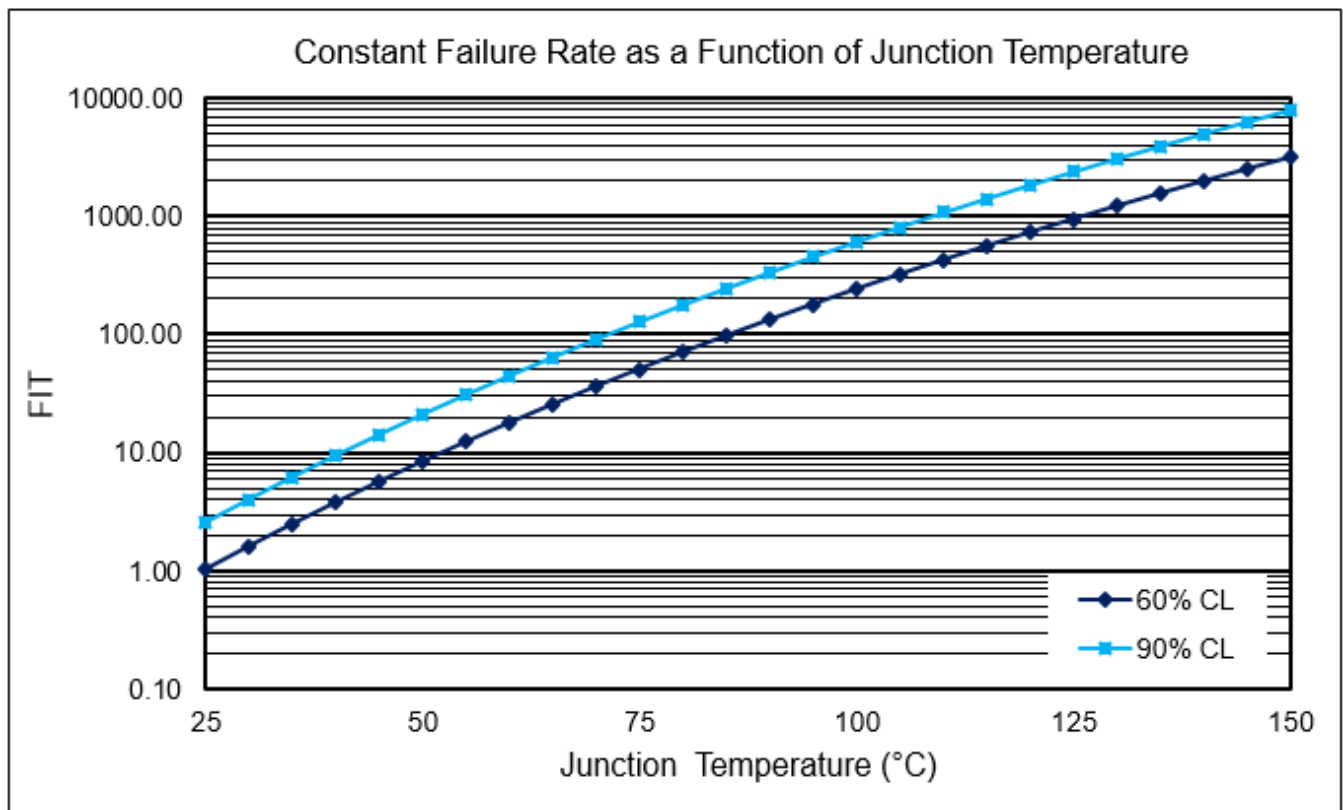
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.22E+06	752.9	1.33E+06
Constant (Random)	2.54E+07	36.1	2.77E+07



Power Limiters (LMTR)

Description : UltraCMOS Power Limiters.
 Products in Family : PE45140, PE45361, PE45450
 Process Technology : UltraCMOS® 5, UltraCMOS® 8
 Units Tested : 589

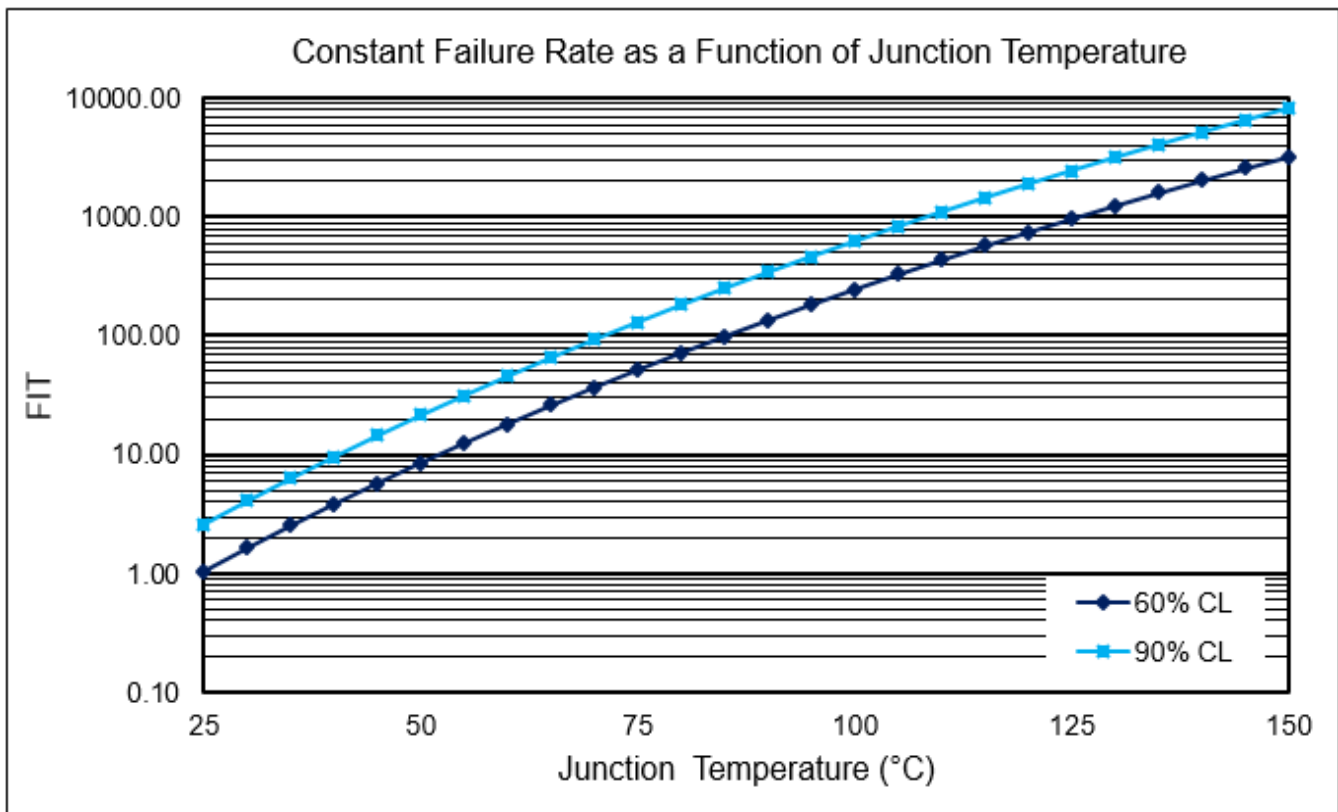
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	7.04E+06	130.2	7.68E+06
Constant (Random)	7.45E+07	12.3	8.13E+07



Monolithic Phase & Amplitude Controller (MPAC)

Description : UltraCMOS RF MPACs.
 Products in Family : PE19601, PE46120, PE46130, PE46140
 Process Technology : UltraCMOS® 5, UltraCMOS® 8
 Units Tested : 565

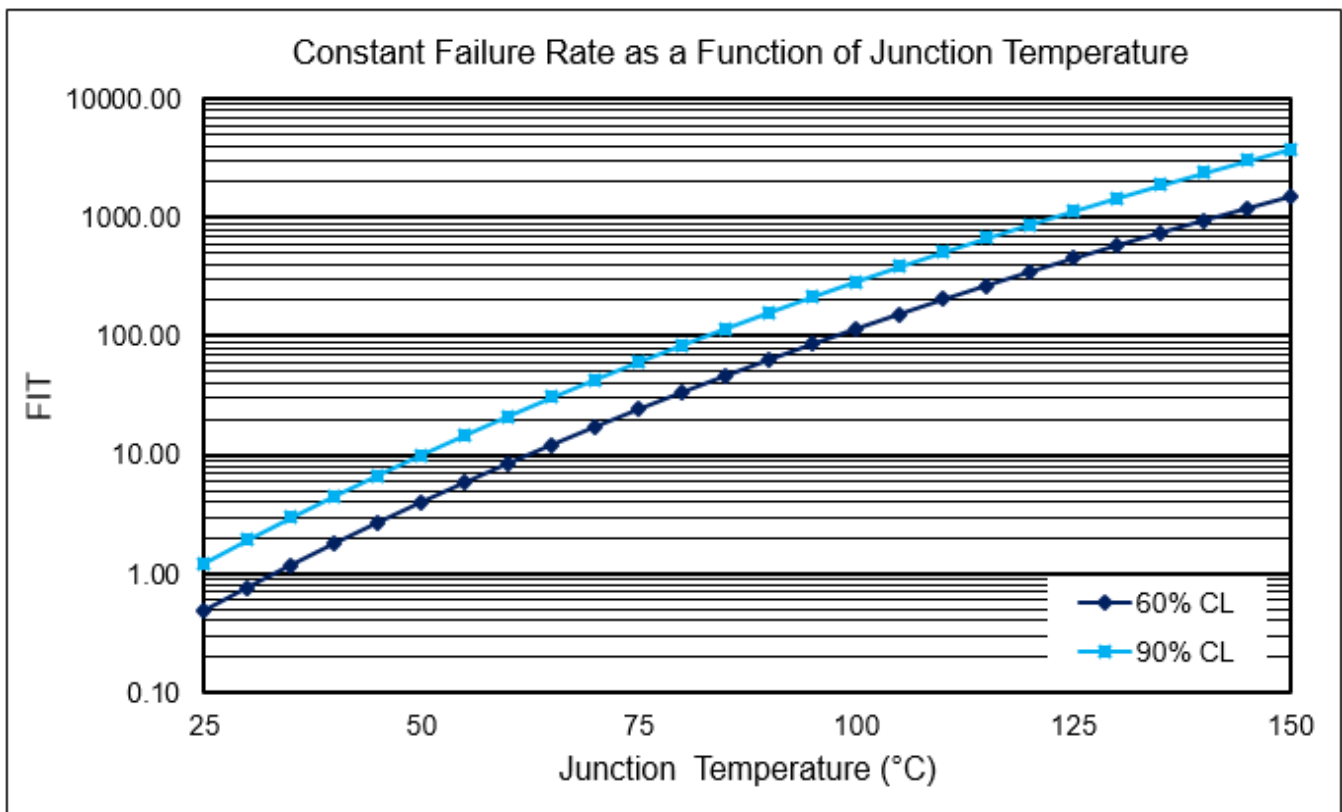
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	7.02E+06	130.6	7.66E+06
Constant (Random)	7.31E+07	12.5	7.98E+07



Mixers (MXR)

Description : UltraCMOS MOSFET quad array broadband and tuned mixers.
 Products in Family : PE4120, PE4122, PE4126, PE4134, PE4140, PE4150, PE4151, PE4152, PE41901
 Process Technology : UltraCMOS[®] 2, UltraCMOS[®] 8
 Units Tested : 1,136

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	9.15E+06	100.1	9.99E+06
Constant (Random)	1.57E+08	5.9	1.71E+08



PA Controller (PAC)

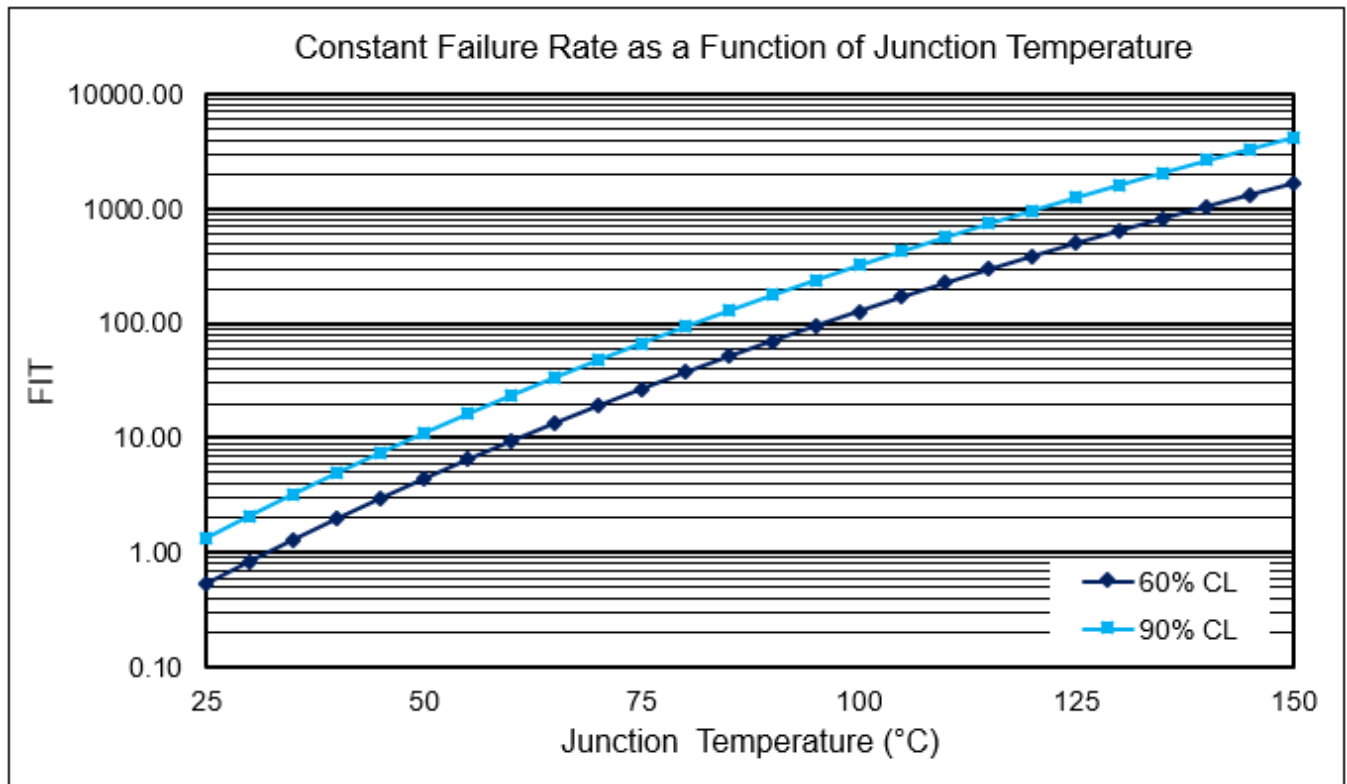
Description : PA Controller controls the PA bias current in PAD modules for RF Front Ends

Products in Family : PE515131, PE515170, PE515190, PE519011

Process Technology : UltraCMOS® 12, UltraCMOS® 12A

Units Tested : 7,482

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	3.01E+07	30.5	3.28E+07
Constant (Random)	1.42E+08	6.5	1.55E+08



Phase Locked-Loop Synthesizers (PLL)

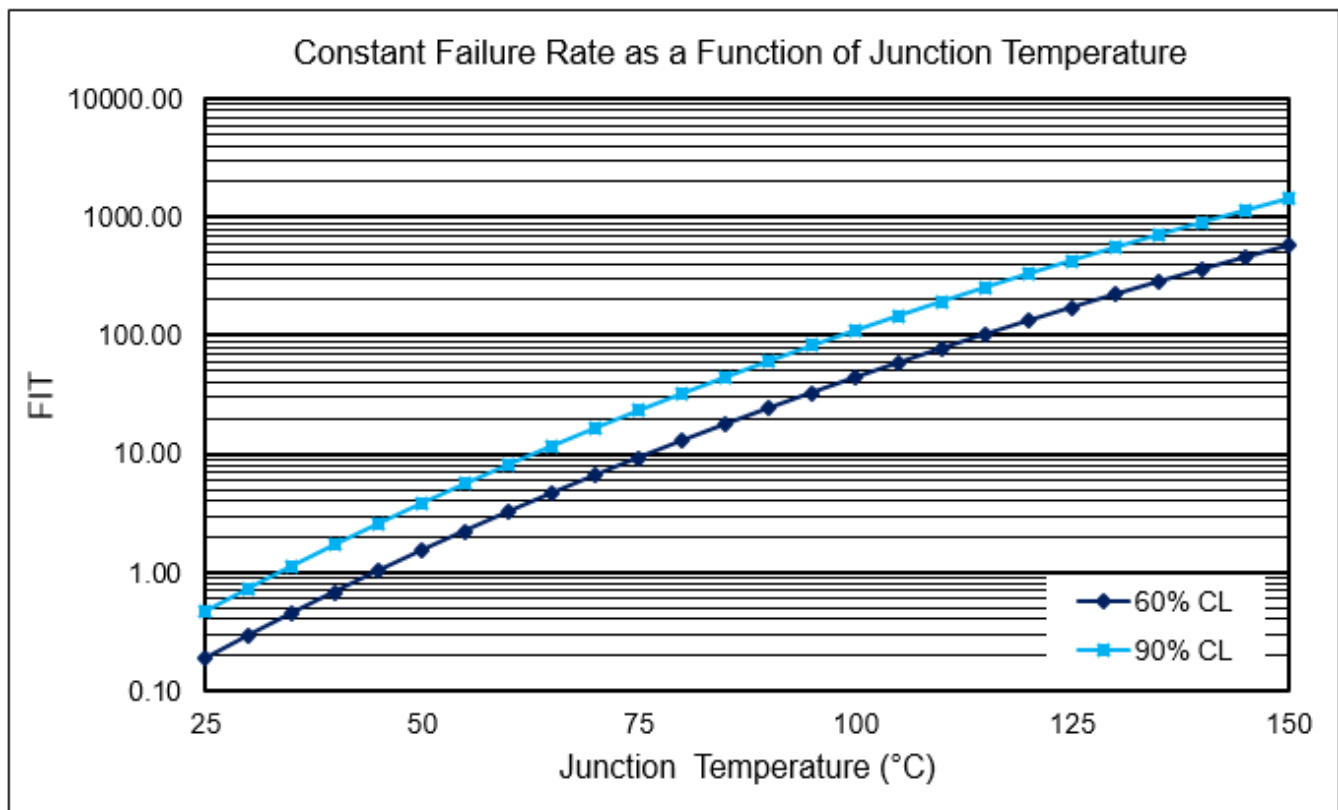
Description : Integer-N, Fractional-N and Delta Sigma Modulated frequency synthesizers for base station, mobile wireless and high reliability space applications.

Products in Family : PE3236, PE33241, PE3335, PE3336, PE33361, PE3341, PE3342, PE83336-21, PE9601, PE9701, PE9702, PE97022, PE9704, PE97042, PE97240, PE9763, PE9763-14, PE97632, PE97640

Process Technology : UltraCMOS® 2, UltraCMOS® 5

Units Tested : 5,846

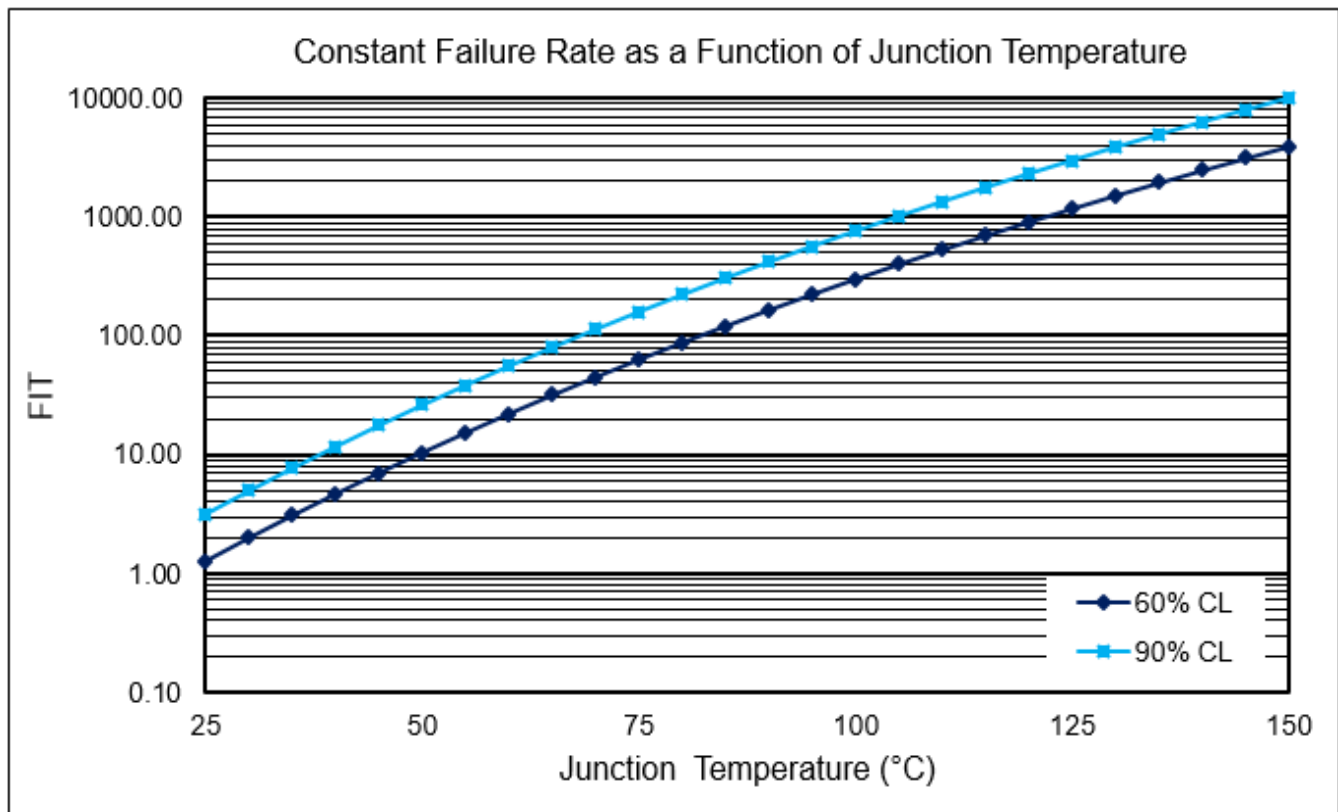
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	2.95E+07	31.0	3.22E+07
Constant (Random)	4.13E+08	2.2	4.51E+08



Phase Shifters (PSH)

Description : UltraCMOS RF Phase Shifters.
 Products in Family : PE44820
 Process Technology : UltraCMOS® 5
 Units Tested : 432

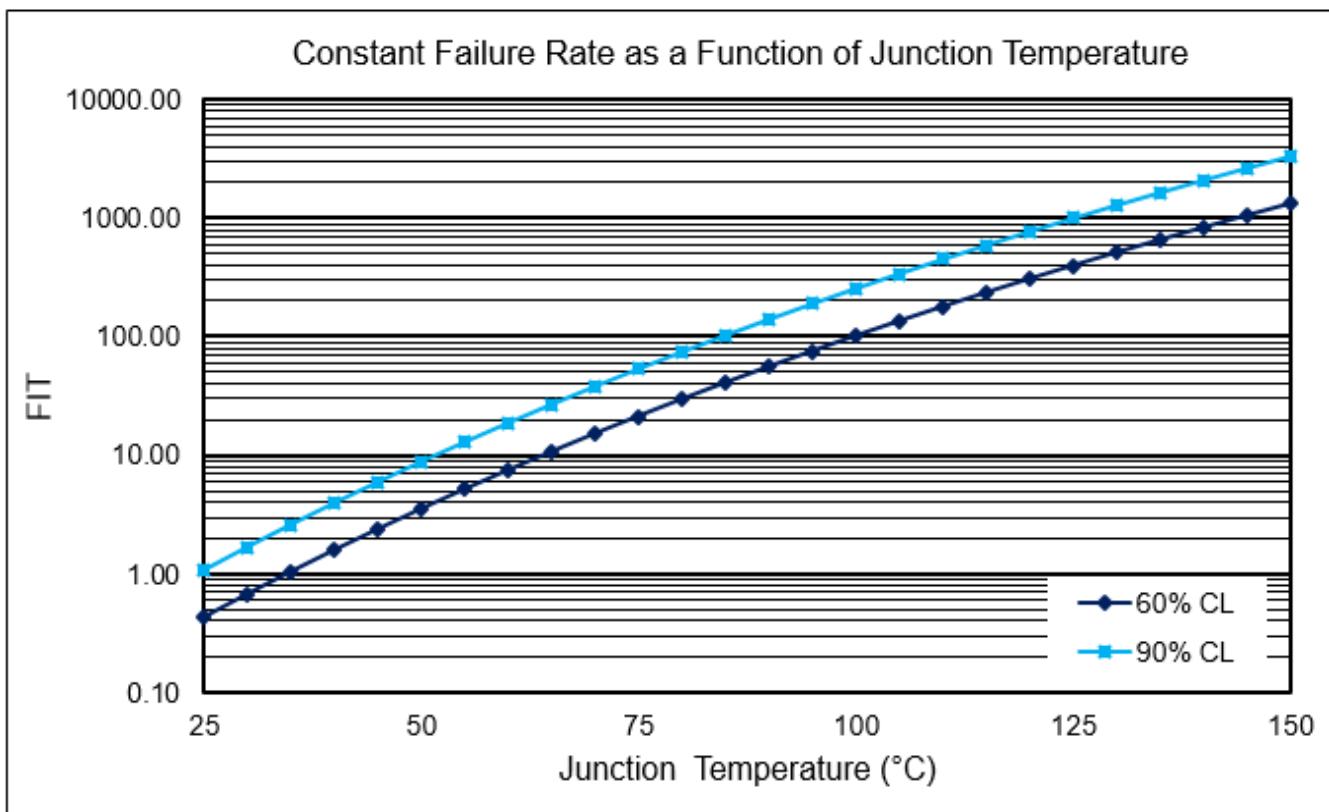
Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	5.37E+06	170.8	5.86E+06
Constant (Random)	6.00E+07	15.3	6.55E+07



Prescalers (PSR)

Description : UltraCMOS RF Prescalers.
 Products in Family : PE3501, PE3503, PE3511, PE3512, PE35400, PE83512, PE9301, PE9303, PE9304, PE9308, PE9309, PE9311, PE9312, PE9313
 Process Technology : UltraCMOS® 2, UltraCMOS® 8
 Units Tested : 2,432

Standard Failure Rate Calculations at 55°C and 60% CL			
	EDH (hours)	FITs	MTTF (hours)
Early Life	1.25E+07	73.5	1.36E+07
Constant (Random)	1.78E+08	5.1	1.94E+08





Reliability Data

(Periodic Testing for the last 8 Quarters)

High Temperature Operating Life (HTOL)

Reference Standards : JESD22-A108
 Test Conditions : $T_A = 125^{\circ}\text{C}$ (A) or 150°C (B)
 : $V_{\text{bias}} = \text{max operating voltage}$
 Test Duration (typical) : HTOL: 1,000 hrs. at (A) or 500 hrs. at (B)
 ELFR: 48 hrs. at (A) or 24 hrs. at (B)

HTOL & ELFR Process Technology	2018 Q3	2018 Q4	2019 Q1	2019 Q2	2019 Q3	2019 Q4	2020 Q1	2020 Q2
55LPx	-	-	-	-	-	0/255	0/88	-
BCD Gen II	0/253	-	-	-	0/954	-	-	-
BCD Lite	-	-	-	-	0/510	-	-	-
UltraCMOS® 10	-	-	-	-	-	-	-	-
UltraCMOS® 11	0/870	0/539	0/166	0/247	0/85	-	-	-
UltraCMOS® 12	0/468	0/157	0/286	0/4,081	0/90	0/162	0/254	0/3,817
UltraCMOS® 12A	-	-	-	0/96	-	-	0/2,525	0/670
UltraCMOS® 13	-	-	-	-	-	-	0/270	0/4,062
UltraCMOS® 13S	-	-	-	0/3,613	-	0/2,217	-	0/2,401
UltraCMOS® 2	0/85	0/85	-	0/85	0/85	0/85	0/85	0/90
UltraCMOS® 3.5	0/77	0/77	-	0/85	0/85	-	0/85	0/85
UltraCMOS® 5	0/109	0/85	-	0/85	-	-	-	-
UltraCMOS® 6	-	-	-	-	-	-	-	-
UltraCMOS® 6.5	-	-	-	-	-	-	-	-
UltraCMOS® 8	-	-	-	-	-	-	-	-

HTOL & ELFR Product Family	2018 Q3	2018 Q4	2019 Q1	2019 Q2	2019 Q3	2019 Q4	2020 Q1	2020 Q2
Amplifier	0/1,092	0/539	0/371	0/4,328	0/175	-	0/2,609	0/4,315
DC-DC	0/253	-	0/81	-	0/1,464	-	-	-
Driver	-	-	-	-	-	-	-	-
DSA	-	-	-	-	-	-	-	0/255
DTC	-	-	-	-	-	-	-	-
LMTR	-	-	-	-	-	-	-	-
MPAC	-	-	-	-	-	-	-	-
MXR	-	-	-	-	-	-	-	-
PAC	0/80	0/80	-	0/96	-	0/77	0/170	0/3,478
PLL	-	-	-	-	-	-	-	-
PSH	-	-	-	-	-	-	-	-
PSR	-	-	-	-	-	-	-	-
Switch	0/437	0/324	-	0/3,868	0/170	0/2,387	0/440	0/3,077

Temperature Cycle (TC)

Reference Standards : JESD22-A104
 Test Conditions : -55°C to +125°C (B)
 : -65°C to +150°C (C)
 Test Duration (typical) : 1,000 cyc. at (B) or 500 cyc. at (C)

TC	2018	2018	2019	2019	2019	2019	2020	2020
Package Family	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2
WLCSP	-	-	-	0/310	0/540	-	-	0/1,546
10L 2x2 FCETSLP	-	-	-	-	-	-	-	-
12L 2x2 QFN	0/45	0/45	-	0/55	0/50	-	0/50	0/50
12L 3x3 QFN	-	-	-	-	-	-	-	-
16L 3x3 QFN	-	-	-	-	-	-	-	-
20L 4x4 FCLGA	-	-	-	0/50	0/150	0/135	0/150	-
20L 4x4 QFN	0/300	0/50	-	0/165	-	-	-	-
24L 4x4 FCLGA	-	-	-	-	-	-	-	0/150
24L 4x4 QFN	-	-	-	-	-	-	-	-
29L 4x4 FCLGA	-	-	-	0/165	-	-	0/150	-
30L 3x3.8 QFN	-	-	-	-	-	-	-	-
32L 4x4 FCLGA	-	-	-	-	0/150	-	0/150	-
32L 5x5 FCLGA	0/1,035	-	-	0/165	0/205	-	0/205	-
32L 5x5 QFN	-	-	-	-	-	-	0/150	-

Note

- n/a - Reliability data not available. Package (family) not yet qualified at the specified period.
- dash (-) - Test not performed at the specified period.
- * Plastic encapsulated packages had undergone MSL Preconditioning prior to test.

Highly Accelerated Stress Test (HAST)

Reference Standards : JESD22-A110
 Test Conditions : 130°C, 85% RH, 2.27 atm. (A)
 : 110°C, 85% RH, 1.20 atm. (B)
 Test Duration (typical) : 96 hrs. at (A) or 264 hrs. at (B)

HAST	2018	2018	2019	2019	2019	2019	2020	2020
Package Family	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2
WLCSP	-	-	-	0/580	0/394	-	-	0/947
10L 2x2 FCETSLP	-	-	-	-	-	-	-	-
12L 2x2 QFN	0/45	0/45	-	0/55	0/50	-	0/50	0/50
12L 3x3 QFN	-	-	-	-	-	-	-	-
16L 3x3 QFN	-	-	-	-	-	-	-	-
20L 4x4 FCLGA	-	-	-	-	0/150	-	0/150	-
20L 4x4 QFN	-	-	-	0/165	-	-	-	-
24L 4x4 FCLGA	-	-	-	-	-	-	-	0/150
24L 4x4 QFN	-	-	-	-	-	-	-	-
29L 4x4 FCLGA	-	-	-	-	-	-	0/150	-
30L 3x3.8 QFN	-	-	-	-	-	-	-	-
32L 4x4 FCLGA	-	-	-	-	-	-	0/150	-
32L 5x5 FCLGA	0/135	-	-	0/165	0/150	-	0/150	-
32L 5x5 QFN	-	-	-	-	-	-	0/150	-

Note

- n/a - Reliability data not available. Package (family) not yet qualified at the specified period.
- dash (-) - Test not performed at the specified period. HAST may not apply to hermetic packages.
- * Plastic encapsulated packages had undergone MSL Preconditioning prior to test.

High Temperature Storage (HTS)

Reference Standards : JESD22-A103

Test Conditions : Ta = 150°C

Test Duration (typical) : 1,000 hrs.

HTS	2018	2018	2019	2019	2019	2019	2020	2020
Package Family	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2
WLCSP	-	-	-	0/600	0/540	-	-	0/480
10L 2x2 FCETSLP	-	-	-	-	-	-	-	-
12L 2x2 QFN	-	0/154	-	0/85	0/85	-	0/85	0/85
12L 3x3 QFN	-	-	-	-	-	-	-	-
16L 3x3 QFN	-	-	-	-	-	-	-	-
20L 4x4 FCLGA	-	-	-	0/85	0/150	0/90	0/150	-
20L 4x4 QFN	-	0/85	-	-	-	-	-	-
24L 4x4 FCLGA	-	-	-	-	-	-	-	0/85
24L 4x4 QFN	-	-	-	-	-	-	-	-
29L 4x4 FCLGA	-	-	-	-	-	-	0/150	-
30L 3x3.8 QFN	-	-	-	-	-	-	-	-
32L 4x4 FCLGA	-	-	-	-	0/150	-	0/150	-
32L 5x5 FCLGA	0/135	-	-	-	0/205	-	0/205	-
32L 5x5 QFN	-	-	-	-	-	-	0/150	-

Note

n/a - Reliability data not available. Package (family) not yet qualified at the specified period.

dash (-) - Test not performed at the specified period.



Appendix A

(RF Switch Products List)

Switches (ASW, HPSW, ATS & BSW)

Description	: Multi-pole & multi-throw high power handling antenna switch products for Mobile Wireless RF, broadband infrastructure, and Test Equipment /ATE applications.
Products in Family	: PE42020, PE420540, PE420560, PE4210, PE421080, PE421130, PE421141, PE421160, PE421230, PE421240, PE421261, PE421281, PE421292, PE421293, PE421294, PE421321, PE421422, PE421451, PE421453, PE421454, PE421460, PE421510, PE421550, PE421592, PE421603, PE421628, PE421690, PE421711, PE421729, PE421752, PE421812, PE421821, PE421880, PE421941, PE421951, PE421979, PE422020, PE4230, PE4231, PE4232, PE423422, PE4235, PE42359, PE423641, PE4237, PE4239, PE42412, PE42420, PE42421, PE42422, PE42424, PE42430, PE4244, PE42441, PE42450, PE42452, PE4251, PE42510, PE42520, PE42522, PE42524, PE42525, PE42540, PE42542, PE42543, PE42552, PE42556, PE4256, PE4257, PE4259, PE4261, PE426140, PE42615, PE4263, PE42633, PE426331, PE42641, PE426412, PE426482, PE42650, PE42660, PE42672, PE426810, PE42682, PE426823, PE426850, PE426860, PE426880, PE426882, PE42691, PE426911, PE42695, PE42696, PE426960, PE426970, PE4270, PE42721, PE42723, PE42742, PE42750, PE42823, PE42850, PE429002, PE429011, PE42956x, PE4314, PE43701, PE43711, PE613010, PE614910, PE614912, PE636030, PE636040, PE84140, PE84244, PE926C31, PE926C32, PE9354, PE94257, PE95420, PE95421
Process Technology	: UltraCMOS [®] 2, UltraCMOS [®] 3.5, UltraCMOS [®] 5, UltraCMOS [®] 6, UltraCMOS [®] 6.5, UltraCMOS [®] 8, UltraCMOS [®] 10, UltraCMOS [®] 11, UltraCMOS [®] 12, UltraCMOS [®] 13, UltraCMOS [®] 13S
Units Tested	: 55,357